

Manipulating Phonons Using Phononic Crystals: Reducing the Thermal Conductivity of Silicon

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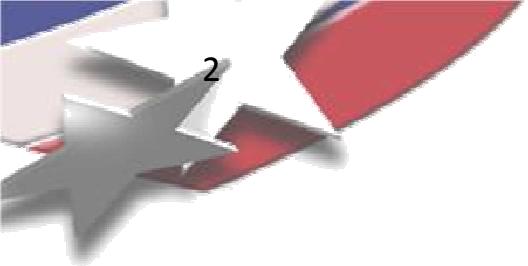
Outline

➤ *Phononic Crystals*

- *Why Phononic Crystals (PnCs)?*
- *Bandgaps in PnCs*
- *RF Applications of PnCs*

➤ *Manipulating Thermal Phonons*

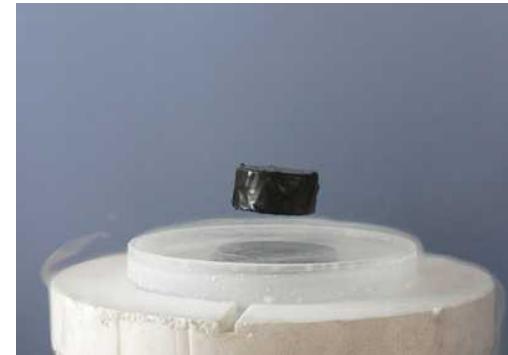
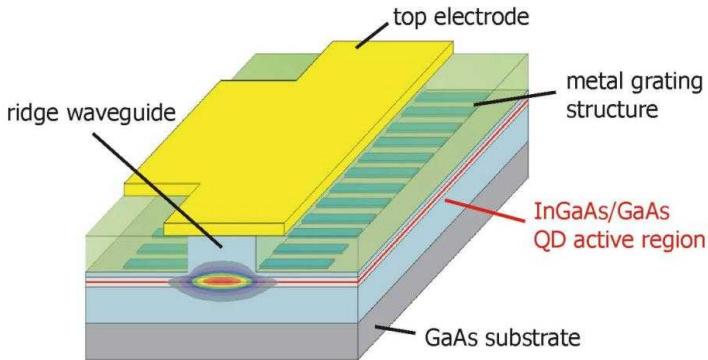
- *Modifying Thermal Conductivity (κ)*
- *Realizing Ultra-Low κ Si*
- *High ZT Devices in Silicon using PnCs*



Motivation:

Manipulating the Propagation of Phonons

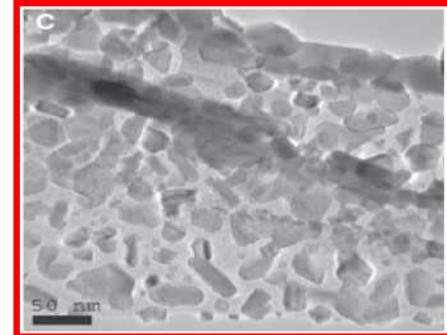
- **Who Cares? (Why?)**
 - **Nonradiative relaxation in QW's**
 - *Cap on SS-laser efficiency*
 - *Cap on SSL device efficiency*
 - **Spin wave relaxation**
 - *Stability of spintronics*
 - *Quantum computing*
 - **Superconductivity**
 - *Binding of Cooper pairs*
 - *Phonon bottleneck*
 - *Hi-TC*
 - **Quantum Friction**
 - **Indirect Bandgap Semiconductors**
 - **Electronics**
 - *ZT figure of merit*
 - *TE scavenging/TE-cooling*



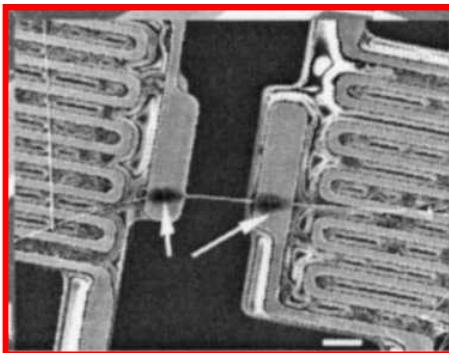
Manipulating the Phonon Population

➤ Current Approaches (How?)

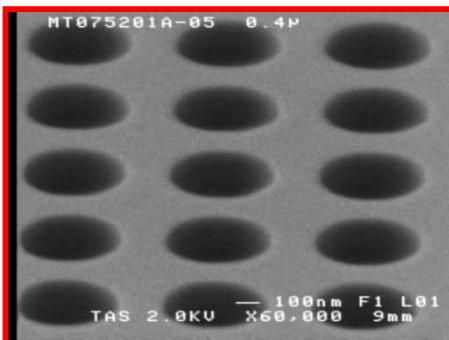
- **Surface scattering: roughening the surface to increase phonon scattering**
 - *Affects only surface propagating modes*
 - *Acts only on a narrow spectrum $\Delta\lambda \sim$ roughness length scale*
 - *Non-deterministic*
- **Grain boundary/impurity scattering:**
 - *Highly non-deterministic*
- **Nanowires/meshes: waveguide cutoff**
 - *Acts only on a narrow thermal spectrum $\lambda \leq$ diameter*
 - *Suppresses low frequency phonons, rather than THz phonons*



Poudel, *et al.*, Science 320, 634 (2008)



Hochbaum, *et al.*, Nature 451, 163 (2008)



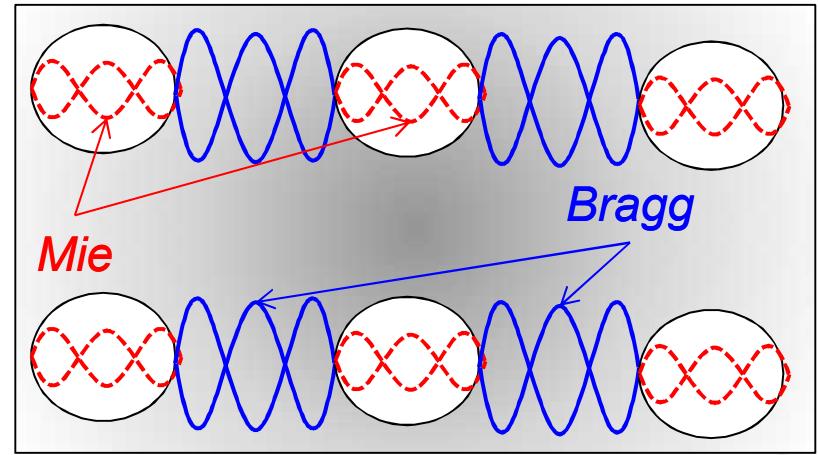
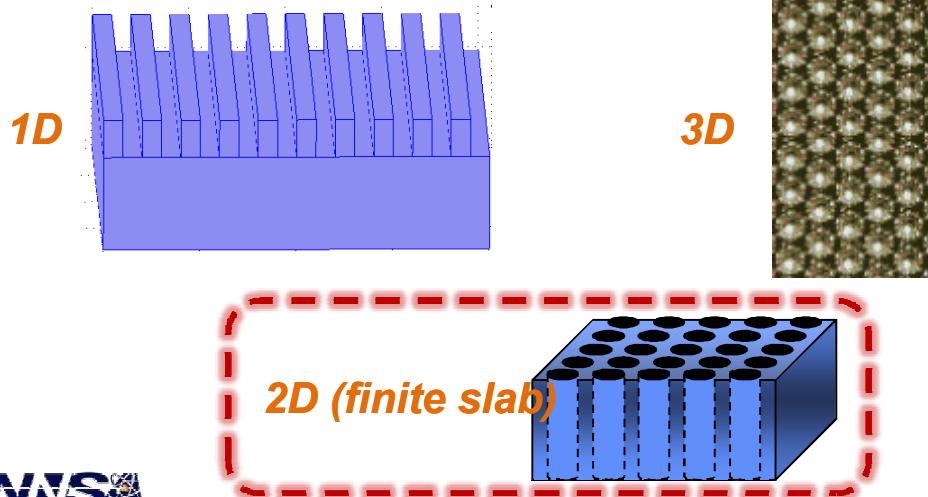
Su, *et al.*, APL 96, 053111 2010

What are Phononic Crystals?

A PnC is a periodic arrangement of elastic materials that can scatter phonons of comparable wavelength

- **How does it work?**

- **Caused by a superposition of Mie and Bragg resonances in the periodic lattice**
- **Requires sufficient acoustic impedance contrast**
- **Allows for full 3D macro- to micro-scale control of phonon propagation**



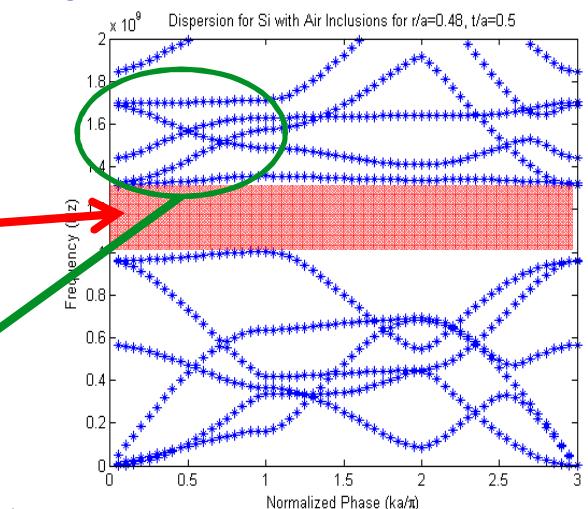
What are Phononic Crystals?

- Properties of Phononic Crystals (PnCs)

- Engineered phononic dispersion
- Phononic bandgap
- Anomalous dispersion (flat and negatively-sloped bands)

$$n(\omega_{k,s}) = \frac{1}{\exp(\hbar\omega_{k,s}/k_B T) - 1}$$

Bulk

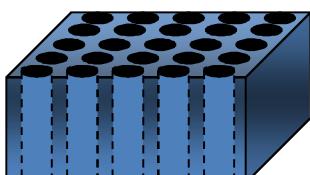


- Phononic Density of States (DOS)

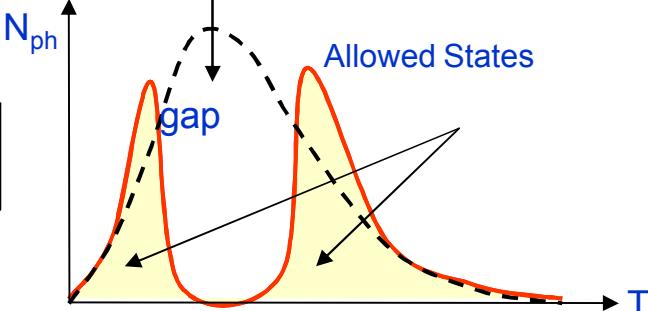
DOS is the number of allowed modes of the material at a given frequency.

- Redistribution of the bulk DOS possible due to modified phonon dispersion.
- Bandgap creates a range of frequencies with zero states, enhanced DOS at the higher and lower edges.

PnC



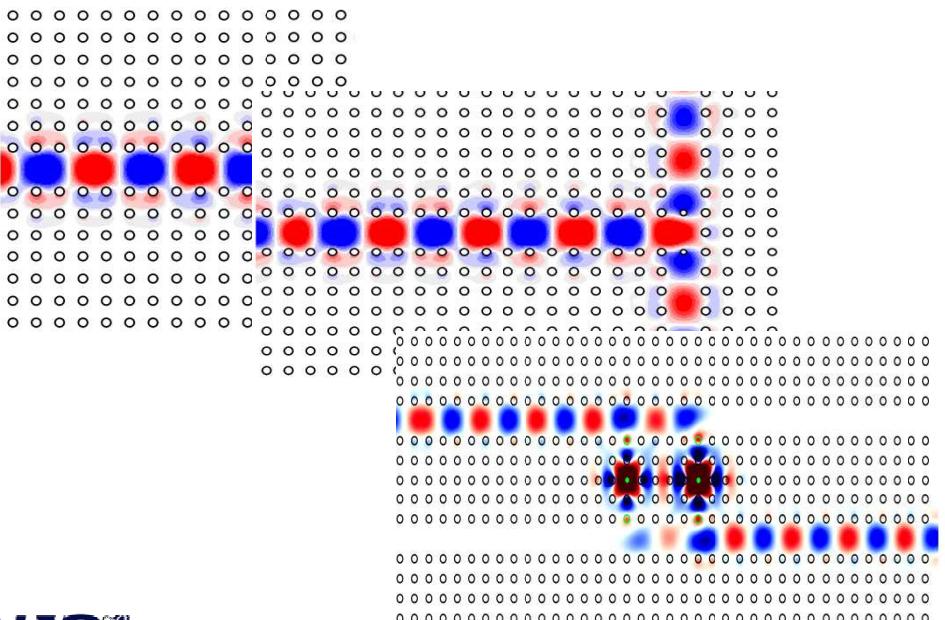
Forbidden States



Why Phononic Crystals?

Why are we interested in the PnC—PhC analogy?

- **Wealth of literature on PhCs that can be used as a first iteration for the design and study of PnC applications**

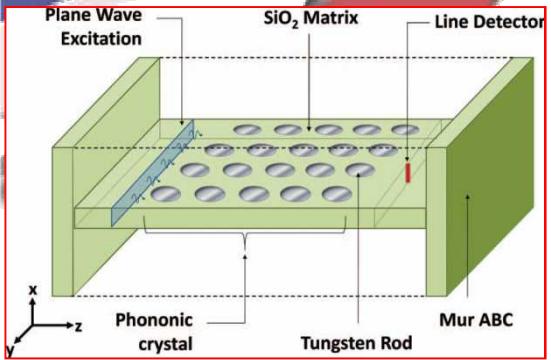


Photonic Crystals (PnC)	Phononic Crystals (PhC)
Refractive index mismatch	Velocity and density mismatch
Integration of lasers and photodetectors problematic	Micromachined integration of piezoelectric or capacitive couplers
3D required for full control	2D (+vacuum) required for full control
Inherently linear	Inherently non-linear
2 nd order coupled vector equations with 2 polarizations	2 nd order coupled vector equations with 3 polarizations
Usually isotropic constitutive parameters	Usually anisotropic constitutive parameters

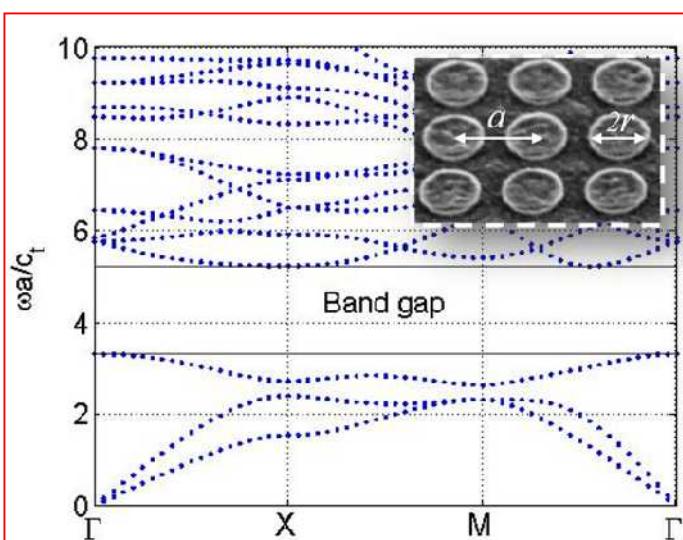
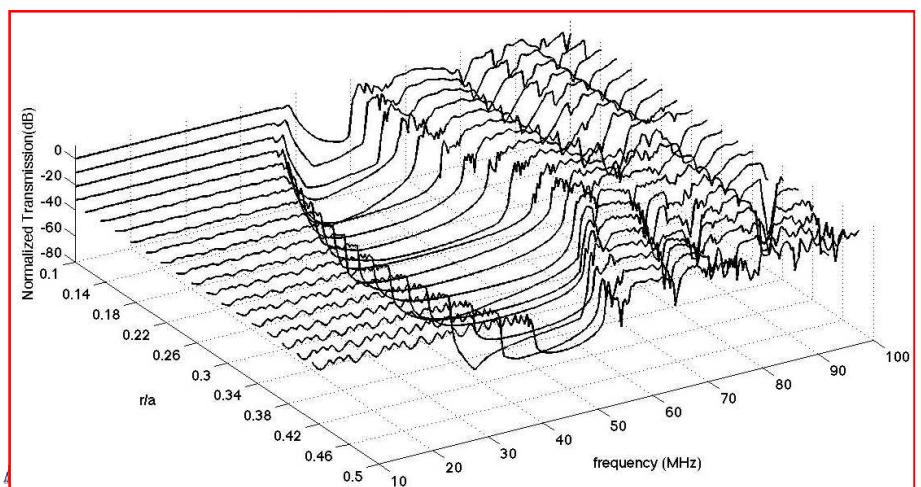
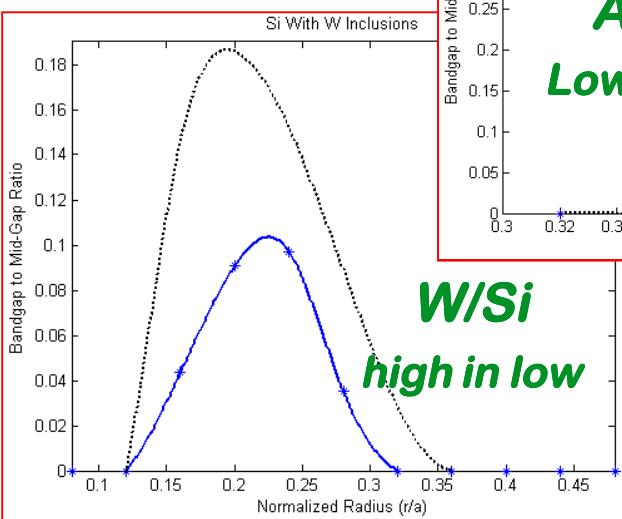
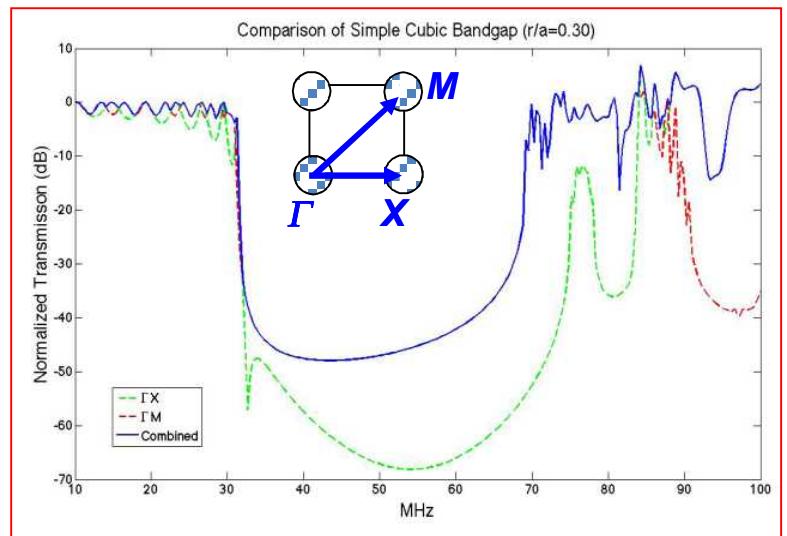
What materials should we use?

- **Ideal photonic materials may not work for phononics!**

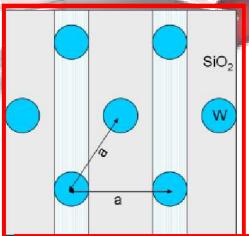
Realizing a Phononic Bandgap



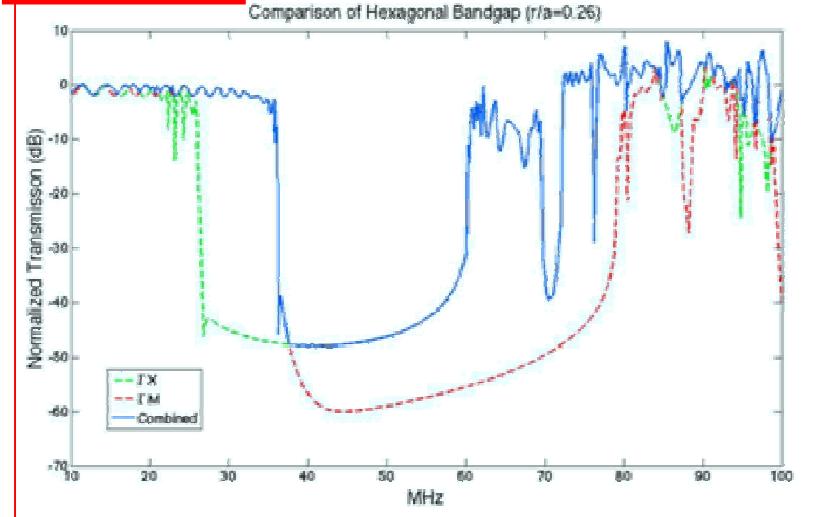
Sqr PnC *PWE*
FDTD



Realizing a Phononic Bandgap



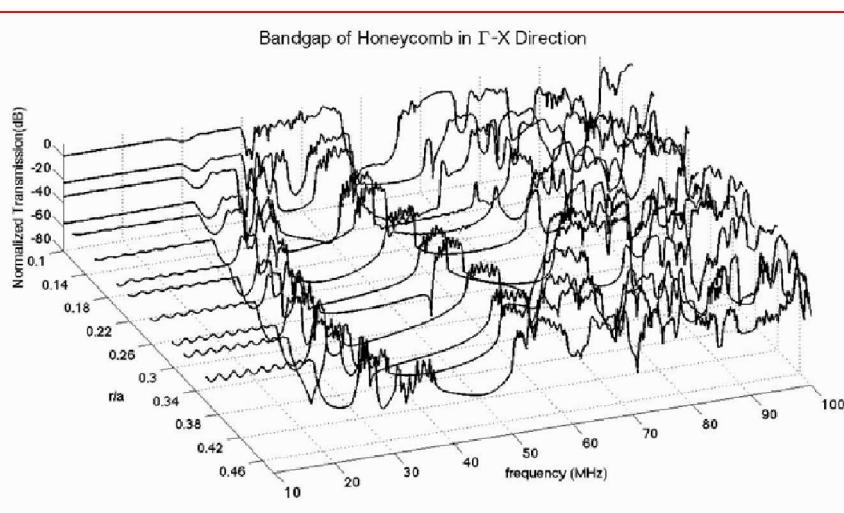
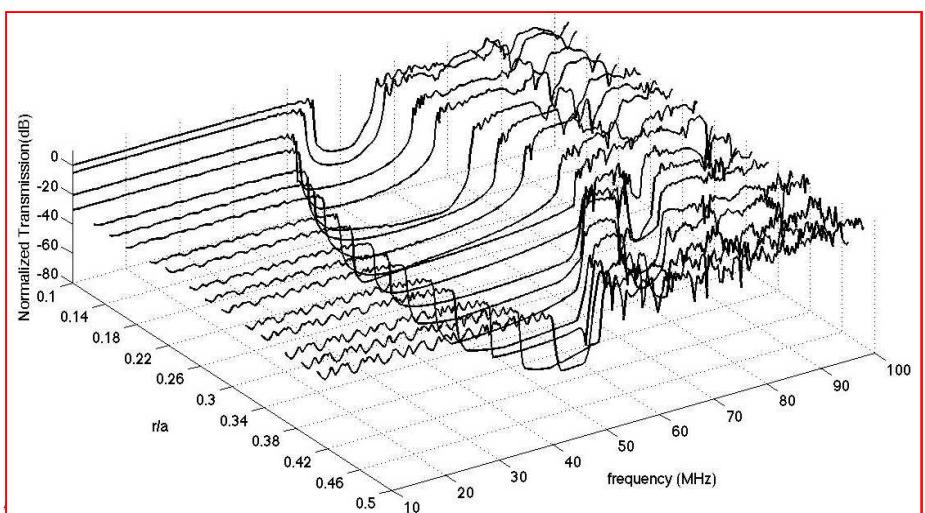
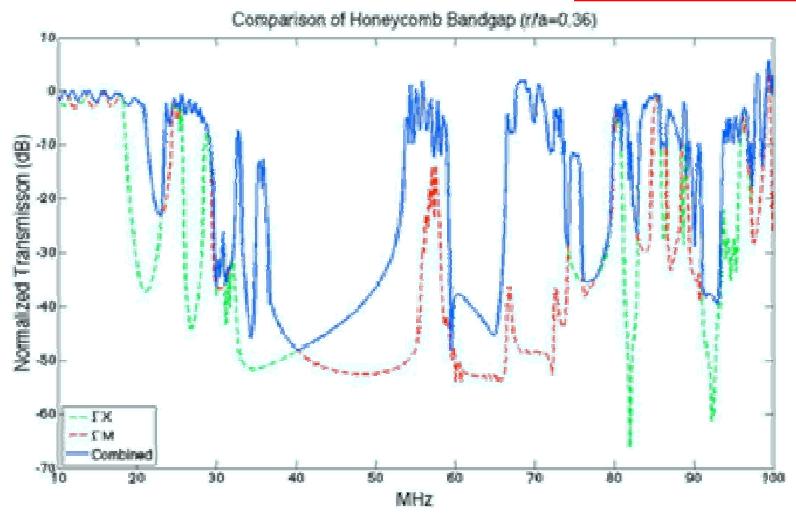
Hex PnC



W/Si



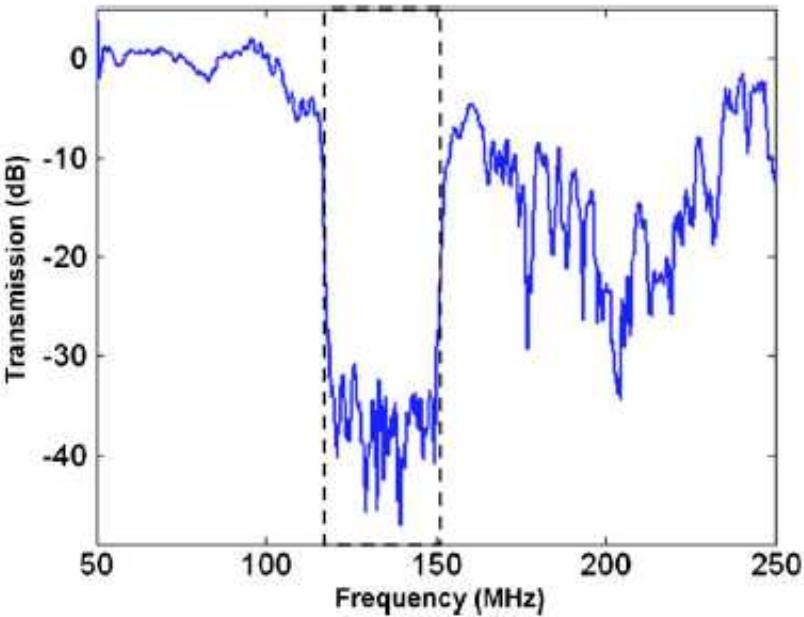
HonC PnC



Solid-Air vs. Solid-Solid PnCs

Solid-Air (Si-air) PnC

- *Hexagonal lattice*
 - *Lattice constant $a = 15\mu\text{m}$*
 - *Hole radius $r/a = 0.43$*
 - *Slab thickness $t/a = 1$*
 - *Bandgap from $f = 118-150\text{MHz}$*



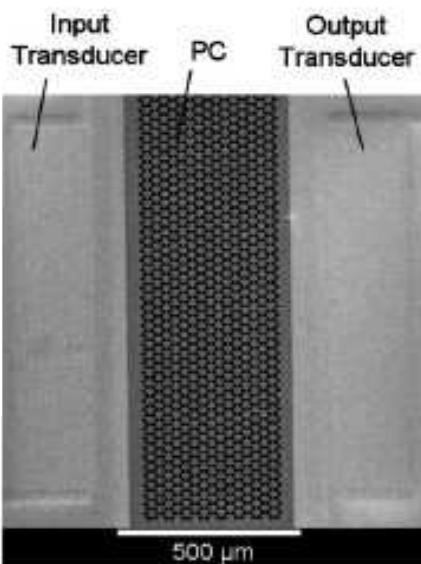
APPLIED PHYSICS LETTERS 92, 221905 (2008)

Evidence of large high frequency complete phononic band gaps in silicon phononic crystal plates

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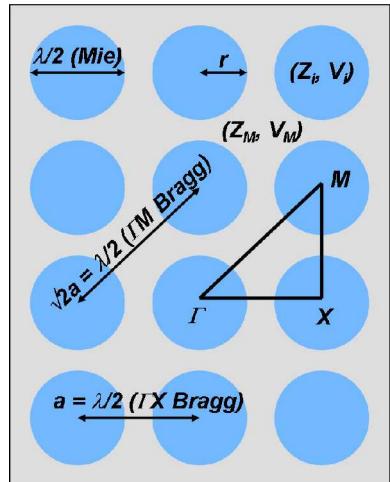
Origin of the Phononic Bandgap

2D PnC can be approximated by a 1D stack of alternating layers

- **Bandgap formation depends on the ratio of the acoustic impedance Z of these two layers**

– $Z_{P2}/Z_{P1} = 2.68$ for Si-air as compared to

$Z_{P1}/Z_{P2} = 3.11$ for Si-W

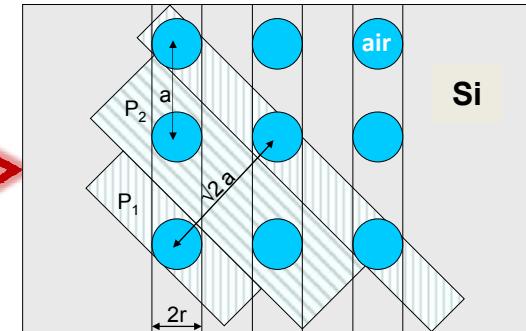
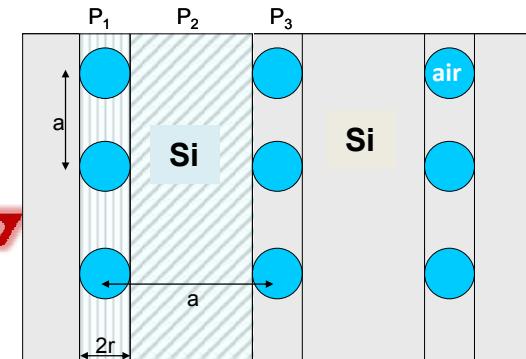


$$f(Bragg)_{\Gamma X} = \frac{V_{avg}}{2a}$$

$$f(Bragg)_{\Gamma M} = \frac{V_{avg}}{(2a)\sqrt{2}}$$

$$f(Mie) = \frac{V_i}{4r} \quad V = \sqrt{\frac{E}{\rho}}$$

$$V_{avg} = \pi \left(\frac{r}{a} \right)^2 V_i + \left(1 - \pi \left(\frac{r}{a} \right)^2 \right) V_M$$

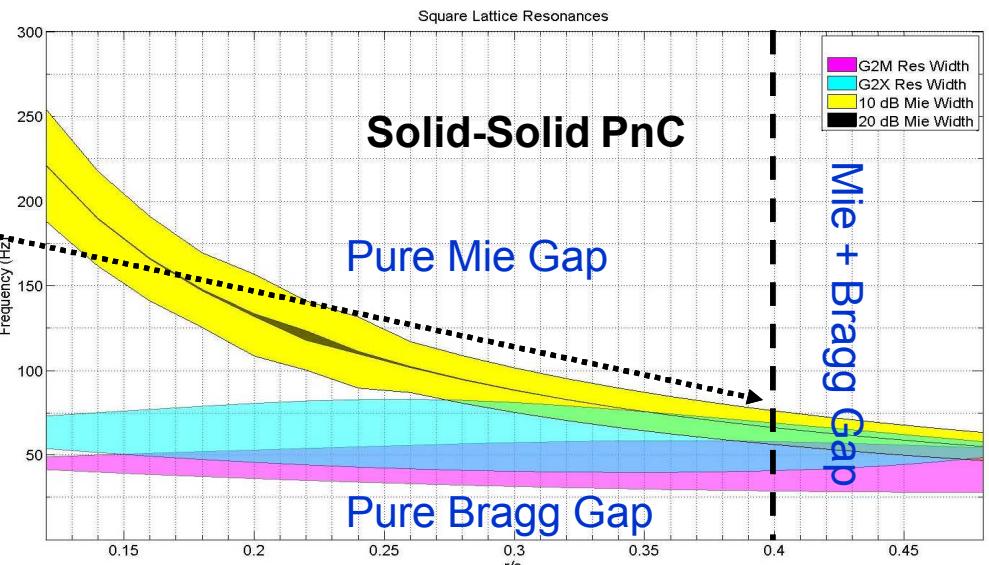
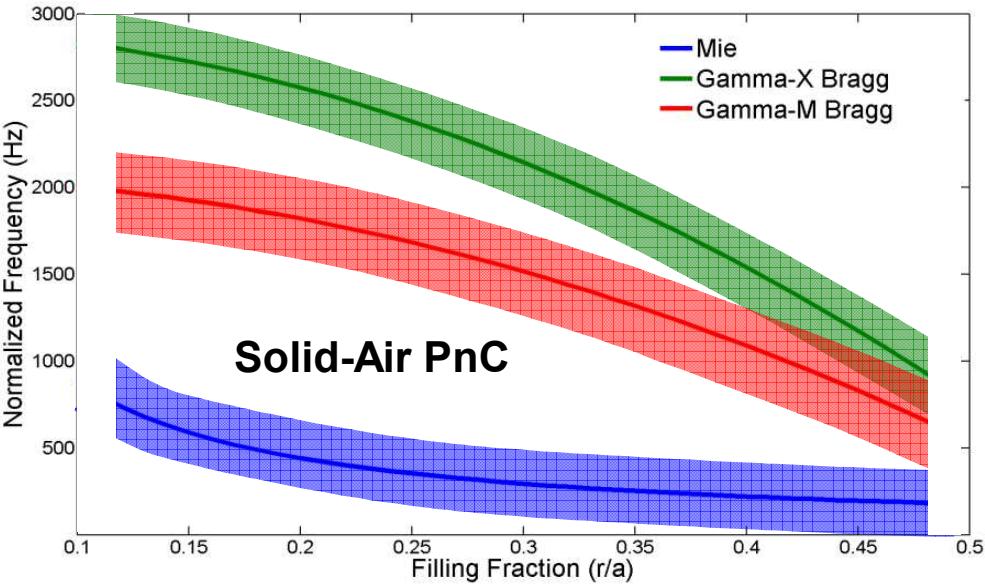
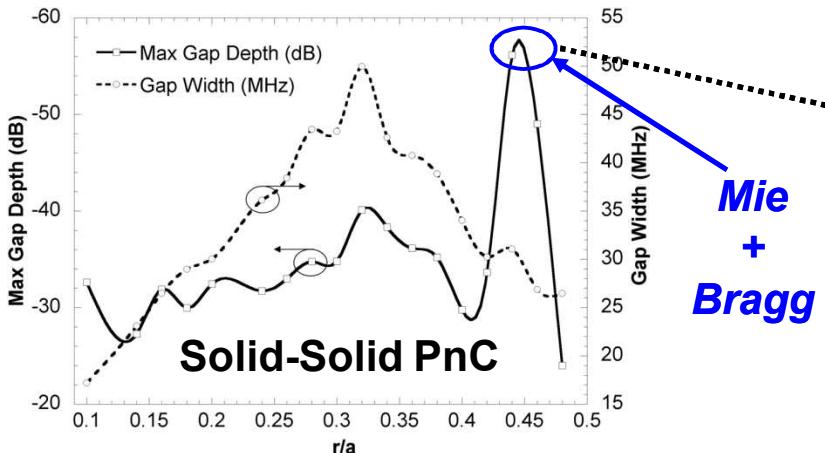


$$Z_{eff1} = ff_1 \cdot Z_{air,W} + (1-ff_1) \cdot Z_{Si},$$

$$\text{where } ff_1 = \frac{\pi r}{2a}$$

Origin of the Phononic Bandgap

- **Solid-air PnC only has Bragg resonance overlap**
 - Large r/a values agree with PWE!
- **Solid-solid PnC has greater overlap of Bragg, Mie resonances**



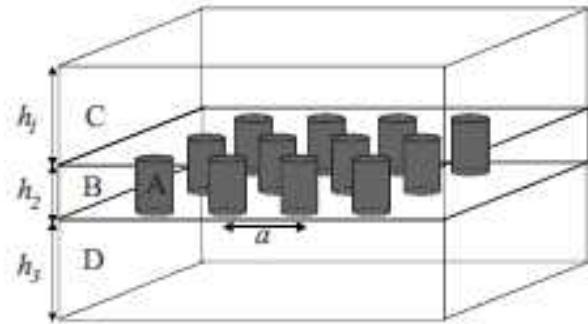
Plane Wave Expansion

- Plane wave expansion (PWE) solves an eigenvalue problem for the modes of a periodic structure
 - *FFT algorithm used to calculate structure factors*

$$\rho(\vec{r}) \frac{\partial^2 u_i(\vec{r}, t)}{\partial t^2} = \sum_{j,k,l} \frac{\partial}{\partial x_j} \left(C_{ijkl}(\vec{r}) \frac{\partial u_l(\vec{r}, t)}{\partial x_k} \right)$$

- Densities

- **Silicon:** 2332 kg/m^3
- **Air:** 10^{-4} kg/m^3
- **Tungsten:** 19250 kg/m^3



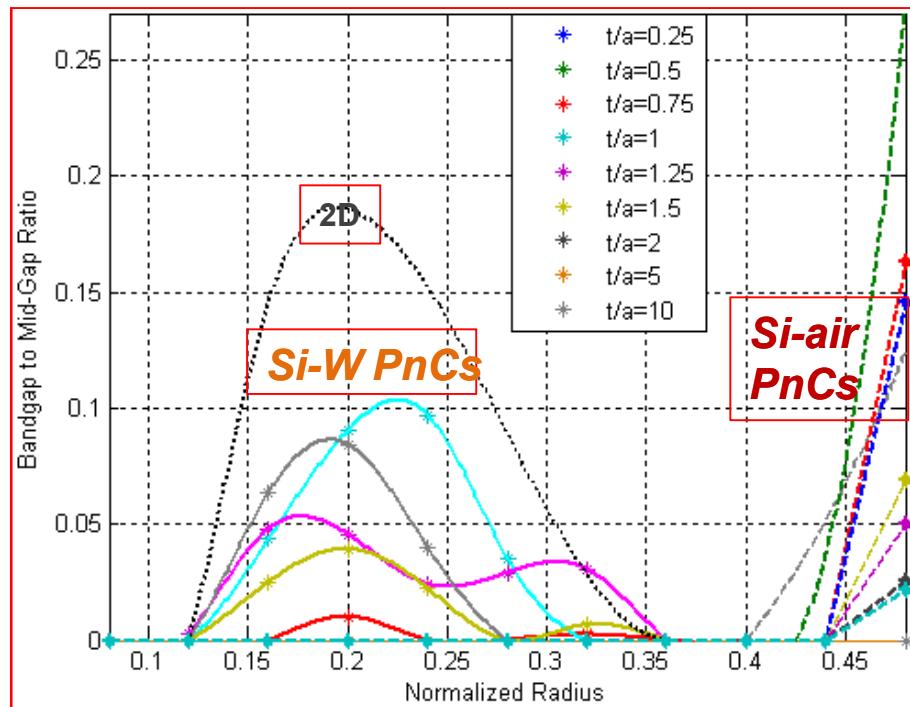
$$C_{air} = \begin{bmatrix} 10^6 & -10^6 & -10^6 & 0 & 0 & 0 \\ -10^6 & 10^6 & -10^6 & 0 & 0 & 0 \\ -10^6 & -10^6 & 10^6 & 0 & 0 & 0 \\ 0 & 0 & 0 & 10^6 & 0 & 0 \\ 0 & 0 & 0 & 0 & 10^6 & 0 \\ 0 & 0 & 0 & 0 & 0 & 10^6 \end{bmatrix}$$

$$C_{Si} = \begin{bmatrix} 16.7 \cdot 10^{10} & 6.39 \cdot 10^{10} & 6.39 \cdot 10^{10} & 0 & 0 & 0 \\ 6.39 \cdot 10^{10} & 16.7 \cdot 10^{10} & 6.39 \cdot 10^{10} & 0 & 0 & 0 \\ 6.39 \cdot 10^{10} & 6.39 \cdot 10^{10} & 16.7 \cdot 10^{10} & 0 & 0 & 0 \\ 0 & 0 & 0 & 7.956 \cdot 10^{10} & 0 & 0 \\ 0 & 0 & 0 & 0 & 7.956 \cdot 10^{10} & 0 \\ 0 & 0 & 0 & 0 & 0 & 7.956 \cdot 10^{10} \end{bmatrix}$$

$$C_w = \begin{bmatrix} 40.9 \cdot 10^{10} & 17.1 \cdot 10^{10} & 17.1 \cdot 10^{10} & 0 & 0 & 0 \\ 17.1 \cdot 10^{10} & 40.9 \cdot 10^{10} & 17.1 \cdot 10^{10} & 0 & 0 & 0 \\ 17.1 \cdot 10^{10} & 17.1 \cdot 10^{10} & 40.9 \cdot 10^{10} & 0 & 0 & 0 \\ 0 & 0 & 0 & 6.74 \cdot 10^{10} & 0 & 0 \\ 0 & 0 & 0 & 0 & 6.74 \cdot 10^{10} & 0 \\ 0 & 0 & 0 & 0 & 0 & 6.74 \cdot 10^{10} \end{bmatrix}$$

Solid-Air vs. Solid-Solid PnCs

- Air- solid PnCs can have large bandgaps, but for a limited range of hole radii
- Solid-solid PnCs have bandgaps for a wider range of inclusion radii
 - Easier fabrication, larger design parameter space

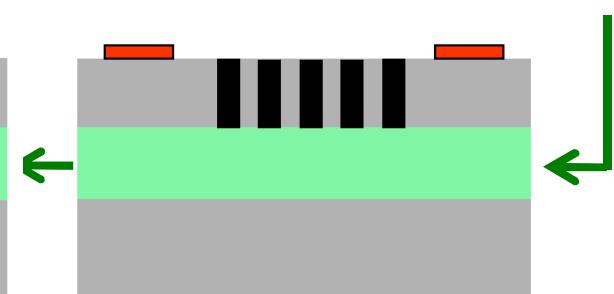
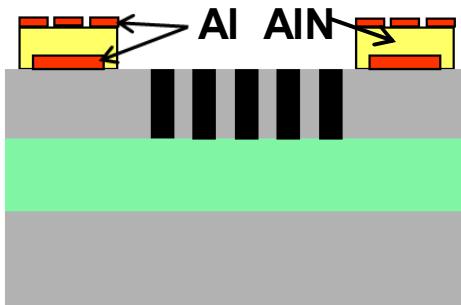
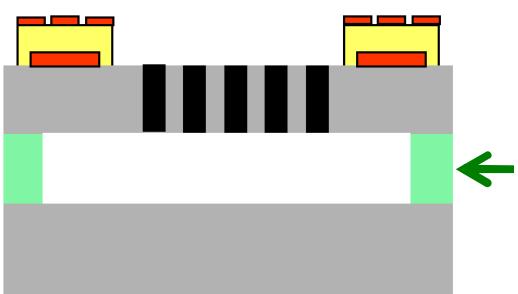
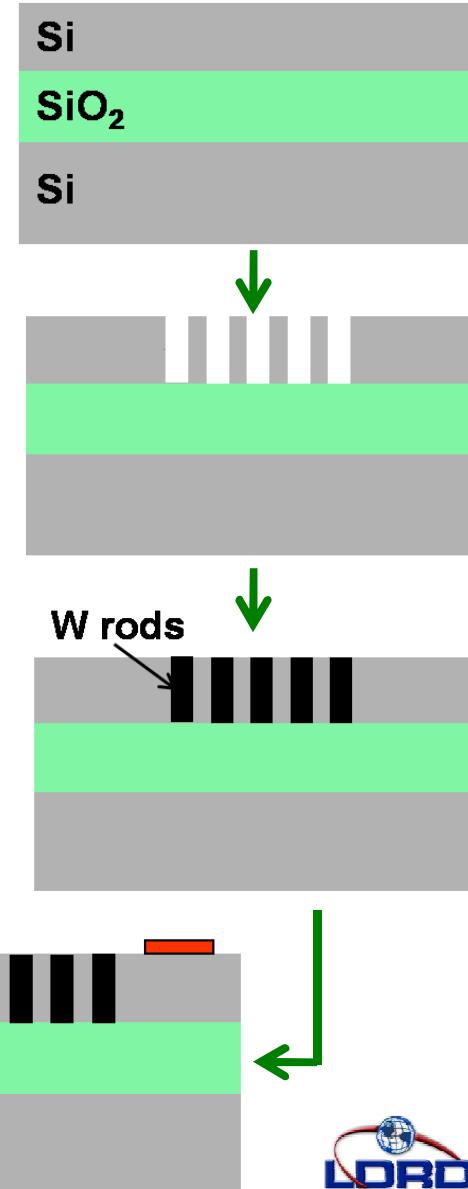


PnC Fabrication

Fabrication of Si-based PnC membranes

- **SOI wafer**

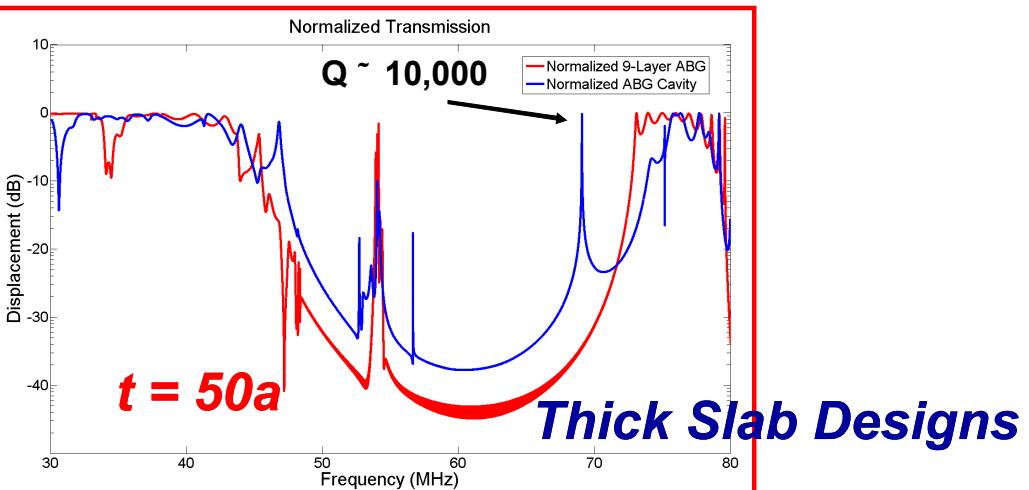
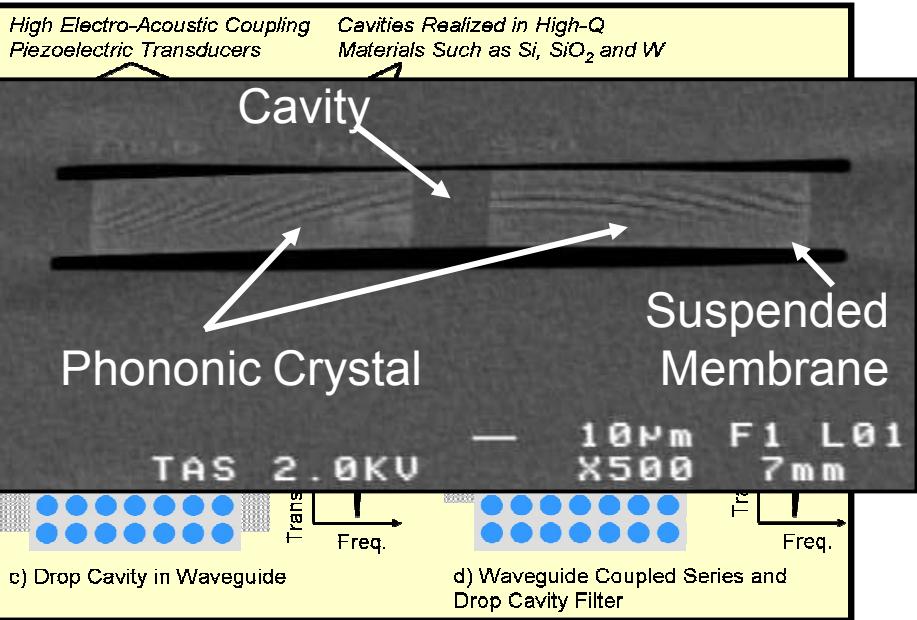
1. *Air holes are patterned and etched*
2. *W is deposited with CVD (solid-solid only)*
3. *Al bottom electrodes are deposited/patterned*
4. *AlN films and Al top electrodes are deposited/patterned*
5. *PnC membrane is released*



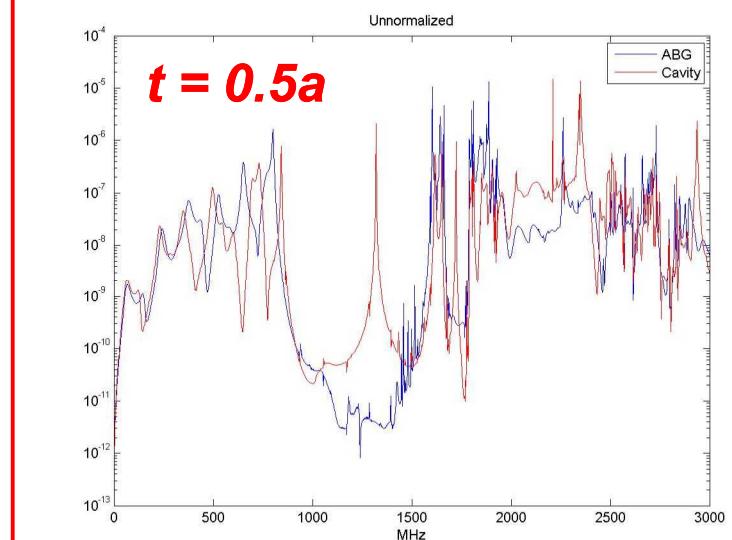
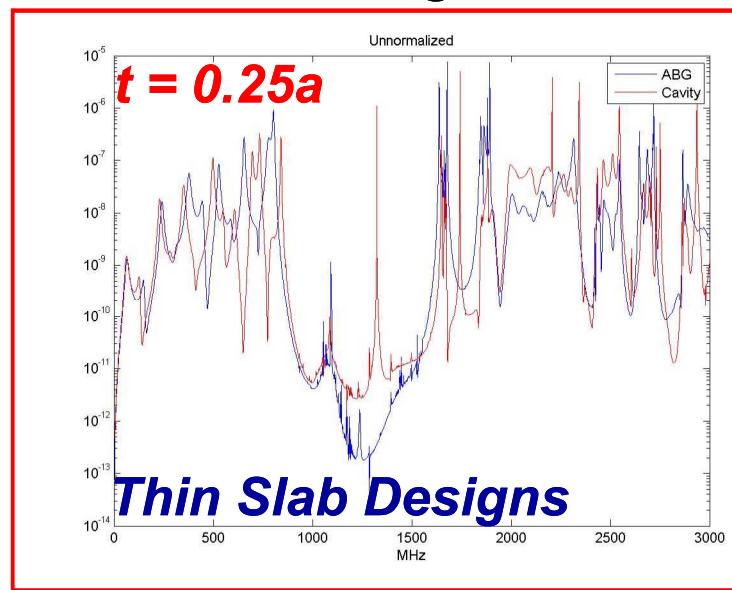
PnC RF Applications

Cellular Phone bands: $\sim 900\text{MHz}$ to $\sim 5\text{GHz}$

Phononic Logic



High Q Cavities

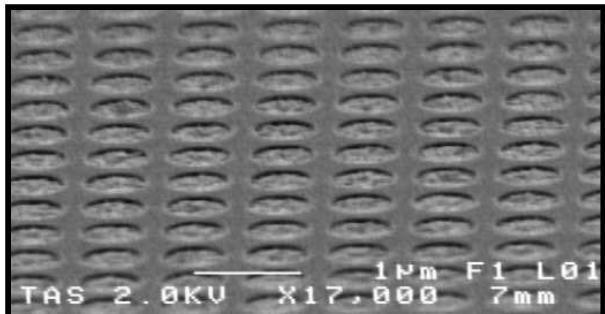


Phononic Signal Processing

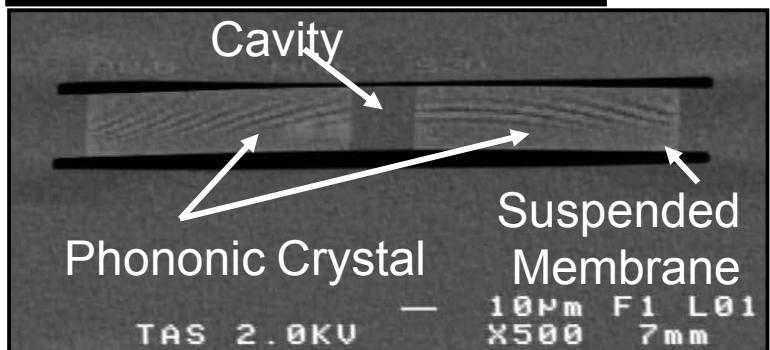
Cellular Phone bands: $\sim 900\text{MHz}$ to $\sim 5\text{GHz}$

Phononic Logic

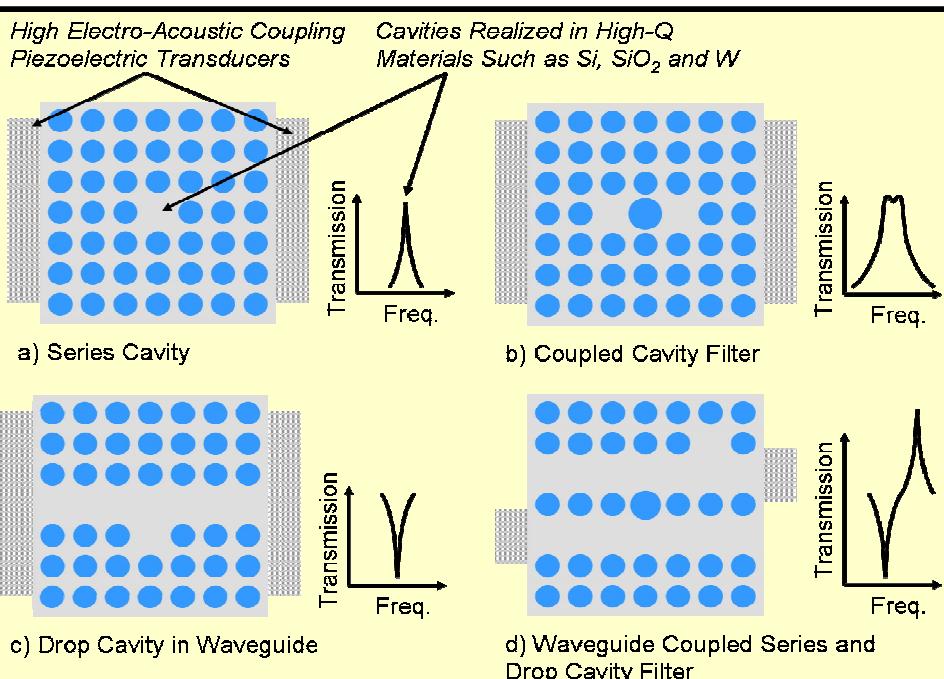
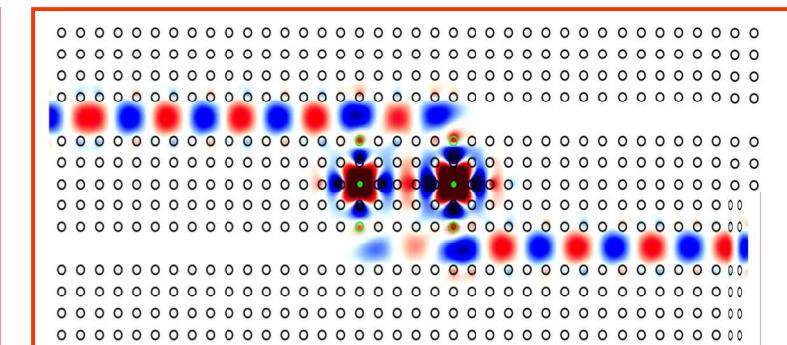
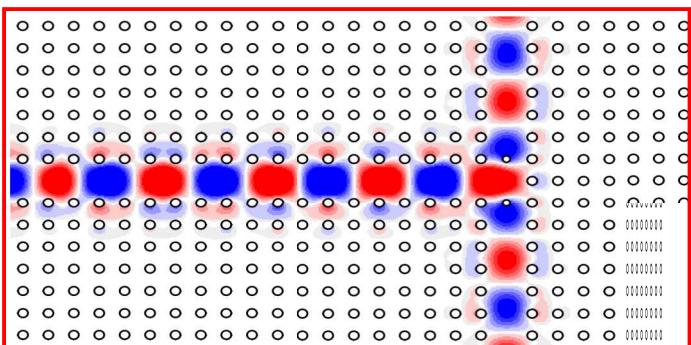
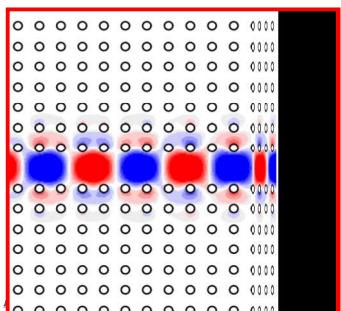
4.25-8.6 GHz PnCs (UHF) 2009



Overtone Cavity
Between Two 5.3
GHz Phononic
Crystals



Phonon Guides



Advantages of PnC Circuitry

❖ Benefits of the Phononic Domain:

- *Integration of multiple components on one chip with little or no losses at a size that is 10⁴-times smaller than current optical or micro-strip technology.*
- *Allows for distributed circuit techniques that are commonly used in microwave circuit design to be applied to lower frequency systems (such as cell phones and WLAN) using acoustic rather than EM waves.*

- Speed of Light = 3×10^8 m/s
- Speed of Sound in SiO₂ = 5.8×10^3 m/s
- Optical Delay Line of 1 μ s = 300 m
- ABG Delay Line of 1 μ s = 5.8 mm
- **ABG delay line is 52,000 times smaller than an optical one!**



Miniature

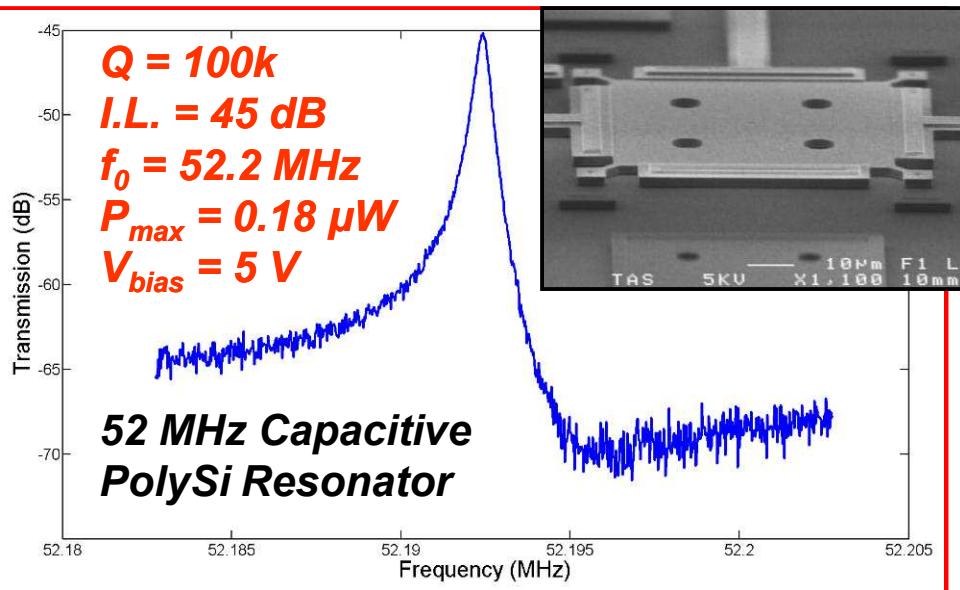
- Filters
- Delay Lines
- Phase Shifters
- Acoustic Signal Processing
- Power Combiners/Dividers

RF Applications:

MEMS Resonator fQ Product/Insertion Loss Trade Off

Capacitive MEMS Resonators

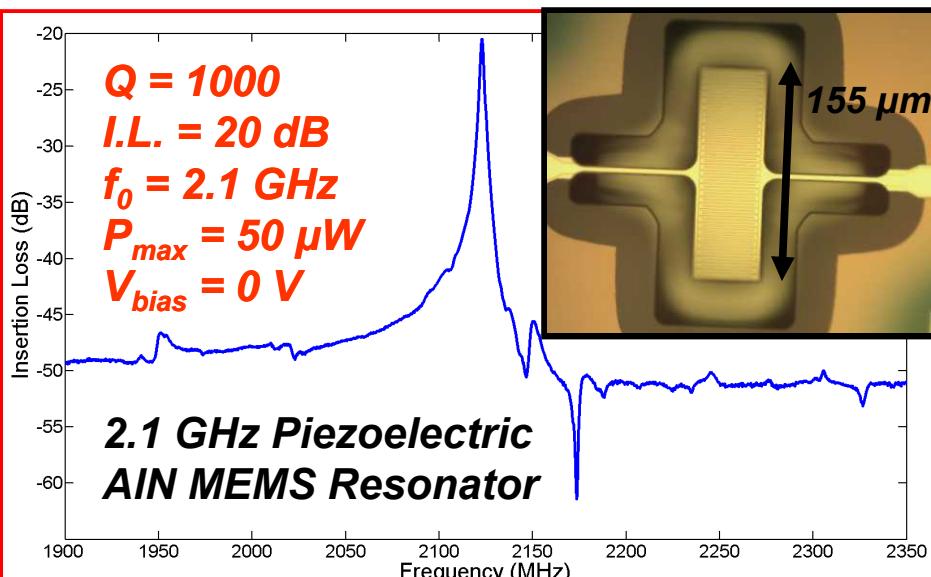
- High fQ product for acoustics (2×10^{13}), but ...
- Weak electro-acoustic transduction leads to high impedance/insertion loss
 - Higher noise, can't match to antennas or off-chip components
 - Arraying and high- K dielectric transduction lead to unmanageable parasitic capacitance
- Force $\approx V^2$ (Low Power Handling)
 - Unsuitable for transmit filters, limits oscillator phase noise and sensor resolution



Piezoelectric MEMS Resonators

- Low impedance (< 50) / Insertion Loss
 - Strong electro-acoustic transduction
 - Easily matched to antenna, off-chip circuits
- Force $\approx V$ (High Power Handling), but ...
- Q limited to a few thousand
 - Material damping in metal electrodes and piezoelectric films, creep, aging

Want Highly Efficient Piezoelectric Transduction + High-Q Materials



RF Applications:

Ultra High Q MEMS PnC Resonators

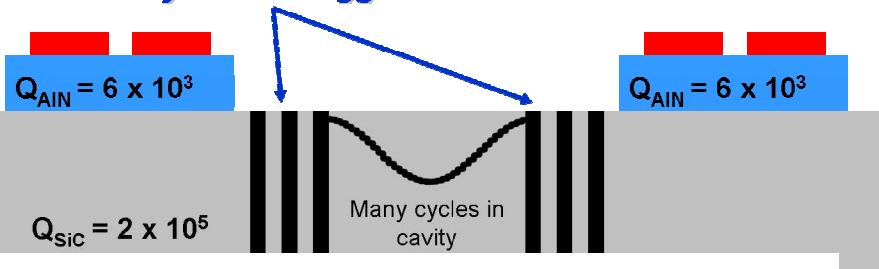
Lithographically Defined Overtone Resonators

- SiC has highest phonon-phonon limited fQ
- Thin film SiC can be deposited, patterned and micromachined using Si IC compatible processes
- Lithographically definable frequencies and bandwidths (scalable to multi-frequency, multi-bandwidth frequency banks)
- Low impedance, high dynamic range AlN couplers
- High stop-band rejection

Phononic Crystal Advantages

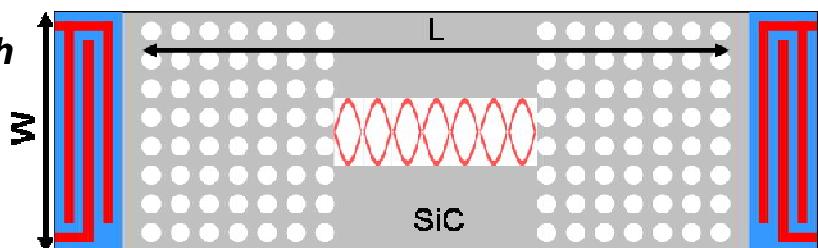
- $\approx 100x$ smaller size, more scalable to arrays
- Lithographically controlled frequency and bandwidth
- Si IC processing/packaging compatible
- Low Impedance, High dynamic range, High isolation
- Co-fabrication with traditional lateral resonator approach

Phononic Crystal or Bragg Acoustic Mirrors



$$Q_{Total} \approx \left[\frac{\frac{1}{Q_{SiC}} + \frac{t_{AlN}}{t_{SiC} Q_{AlN}}}{1 + \frac{t_{AlN}}{t_{SiC}}} \right]^{-1}$$

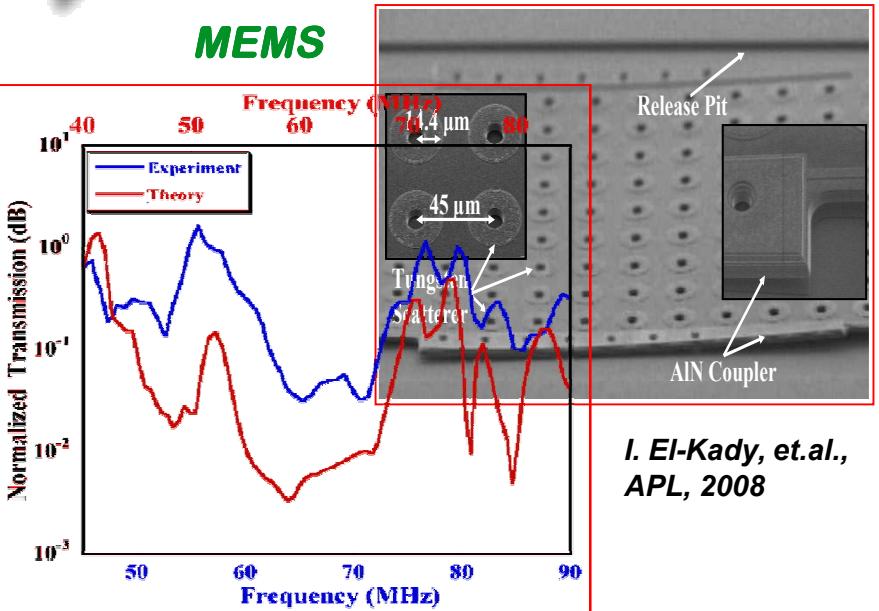
$$Q = 2\pi \frac{E_{Stored}}{E_{Lost}} \frac{Cycle}{}$$



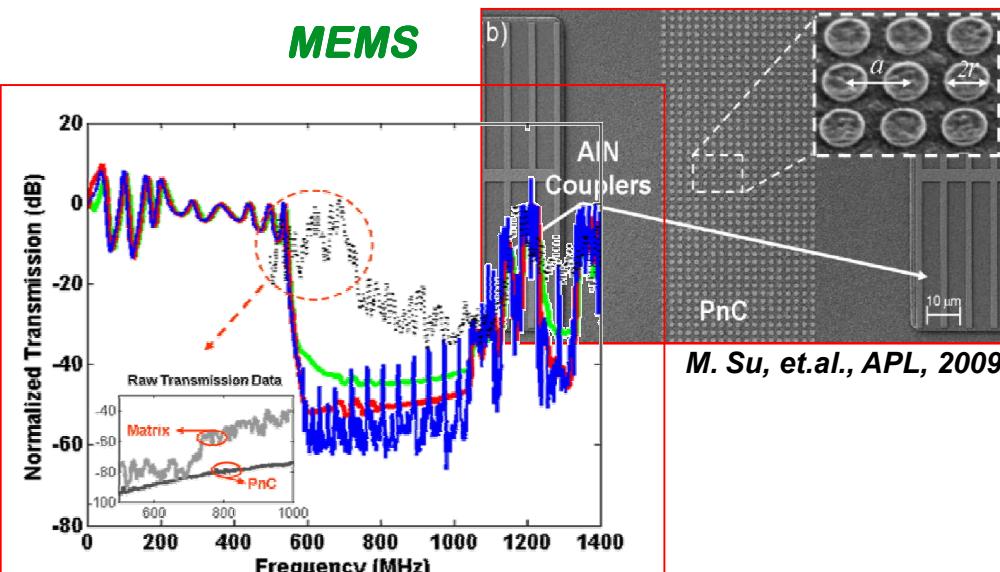
Top Down View of a High-Q PhonC Resonator

PnC Fabrication Roadmap

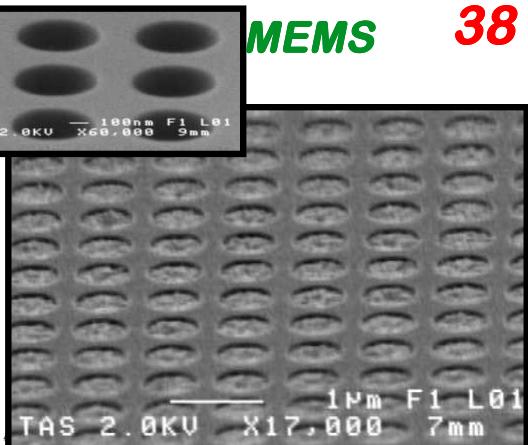
1st MHz MEMS PnC (VHF) 2008



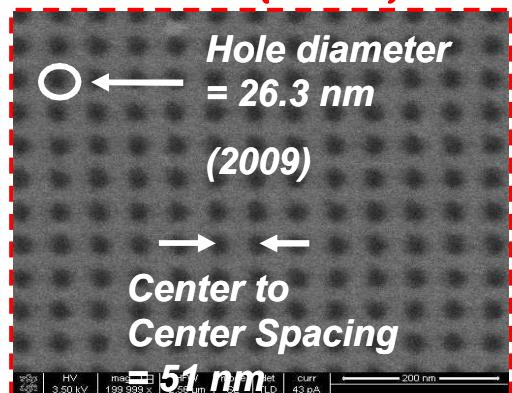
1st GHz MEMS PnCs (UHF) 2009



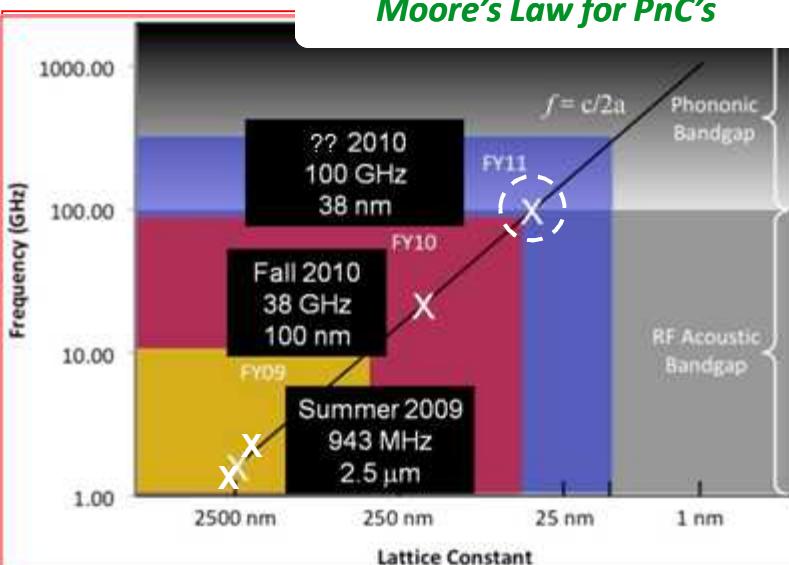
10 GHz PnCs (UHF) 2009



38 GHz PnCs (UHF) 2010

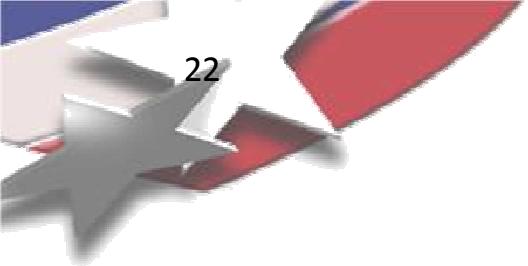


FIB



Outline

- ***Phononic Crystals***
 - ***Why Phononic Crystals (PnCs)?***
 - ***Bandgaps in PnCs***
 - ***RF Applications of PnCs***
- ***Manipulating Thermal Phonons***
 - ***Modifying Thermal Conductivity (κ)***
 - ***Realizing Ultra-Low κ Si***
 - ***High ZT Devices in Silicon using PnCs***

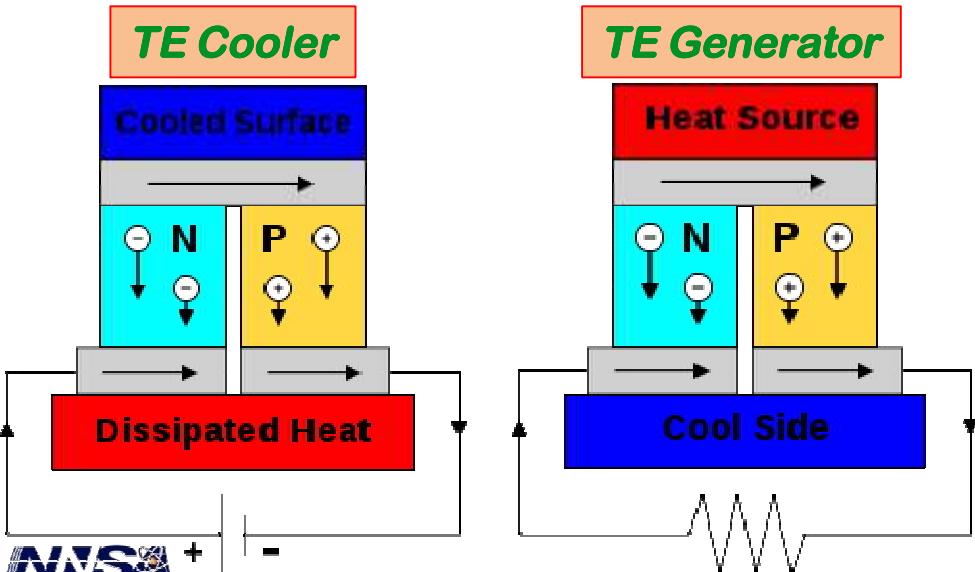


Motivation:

Manipulating Thermal Phonons

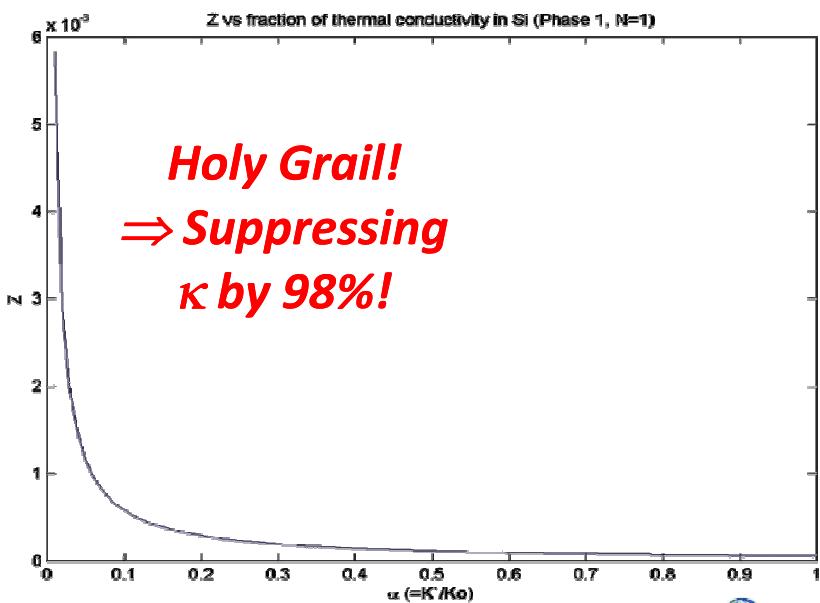
TE Peltier Effect:

- **Cooler:** Apply DC voltage → heat moves from cold-side to hot-side
- **Generator:** Heat gradient → current flow
- **Efficiency:** Quantified by the dimensionless quantity ZT
- **S:** Seebeck coefficient ($\Delta V / \Delta T$)
- **σ :** Electrical conductivity
- **K:** Thermal conductivity ($= K_e + K_{ph}$)



Thermoelectric Figure of Merit

$$ZT = \frac{S^2 \sigma T}{K}$$



Manipulating the Thermal Conductivity of Silicon

- The thermal conductivity is given by

$$\kappa = \frac{1}{6\pi} \sum_j \int_q \frac{\hbar^2 \omega_j^2(q)}{k_B T^2} \frac{\exp\left[\frac{\hbar\omega(q)}{k_B T}\right]}{\left(\exp\left[\frac{\hbar\omega(q)}{k_B T}\right] - 1\right)^2} v_j^2(q) \tau_j(q) q^2 dq$$

$\omega(q)$ is the phonon dispersion.

$v(q) = \partial\omega(q)/\partial q$ is the phonon group velocity,

$\tau(q)$ is the scattering time of the phonons,

q is the wavevector, and the thermal conductivity,

$j = 1, 2, 3$ (1 longitudinal, and 2 transverse).

- We use measured Si dispersion data and fit the data to a 4th degree polynomial for an analytical expression of the phonon dispersion

- In bulk Si, phonon scattering is dominated by Umklapp scattering, impurity scattering, and boundary scattering.

$$\frac{1}{\tau_{Umklapp,j}} = B T \omega_j^2(q) \exp\left[\frac{C}{T}\right]$$

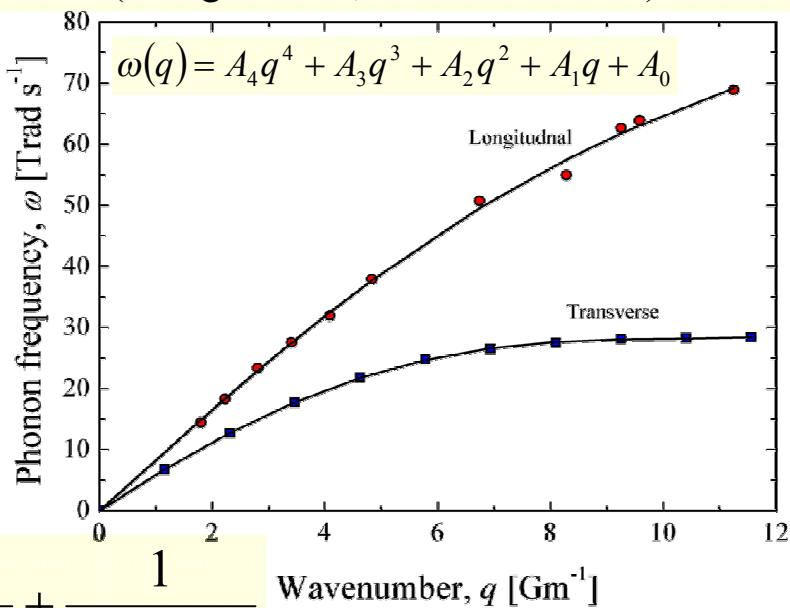
$$\frac{1}{\tau_{impurity,j}} = D \omega_j^4(q)$$

$$\frac{1}{\tau_{boundary,j}} = \frac{v_j(q)}{E}$$

➤ Mattheissen's Rule:

$$\frac{1}{\tau_j(q)} = \frac{1}{\tau_{Umklapp,j}} + \frac{1}{\tau_{impurity,j}} + \frac{1}{\tau_{boundary,j}}$$

- where B, C, D, and E are constants determined by fitting κ to experimental data.



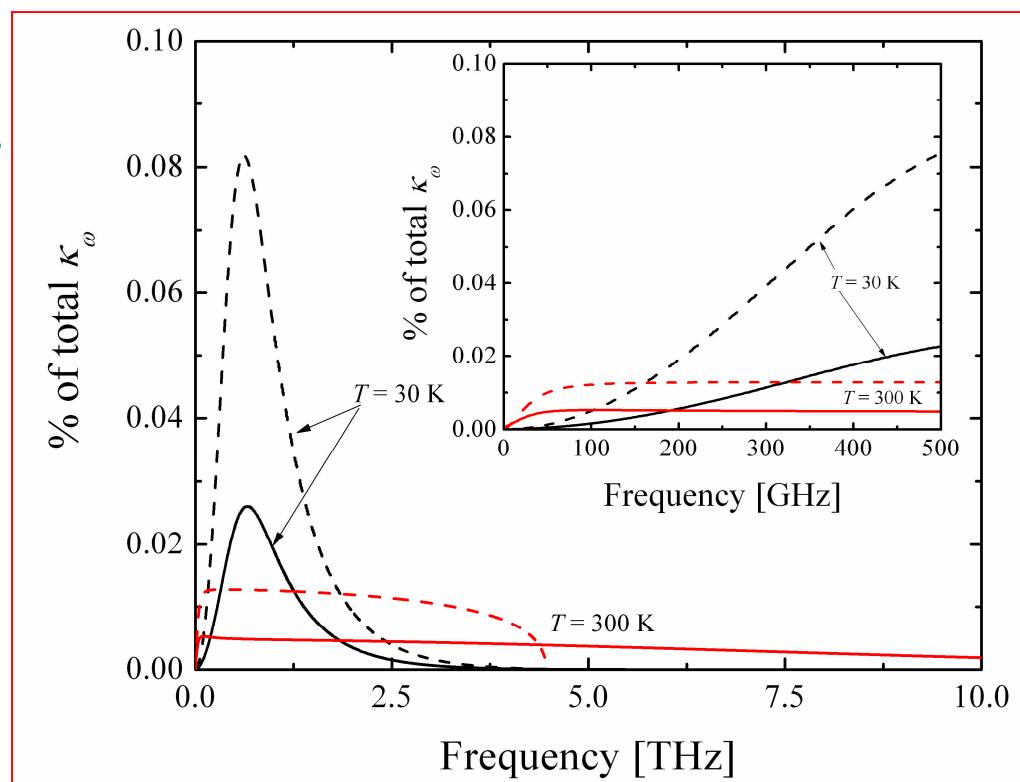
Manipulating the Thermal Conductivity of Silicon

- **The fractional contribution to κ is given by:**

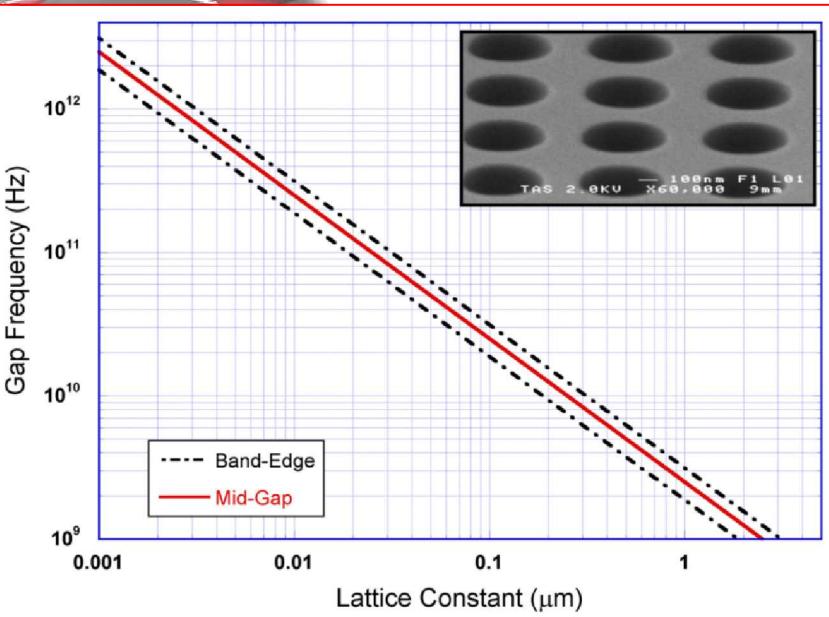
$$\frac{\kappa_{\omega,j}}{\sum_j \sum_{\omega} \kappa_{\omega,j}}$$

- **Fraction of the total spectral thermal conductivity for 30K and 300K. Longitudinal (solid lines) and transverse (dashed lines) contributions.**
- **(inset) Spectral phonon contribution on the range of 0 to 500 GHz.**
- **The major contribution to κ is from 10GHz-4THz phonons**

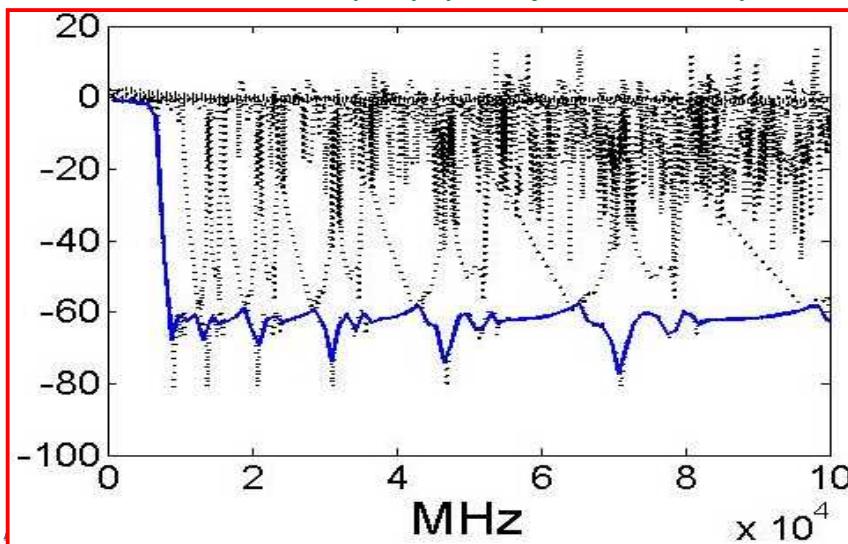
- **Transverse spectral thermal conductivity is multiplied by 2 since we assume degenerate transverse branches.**



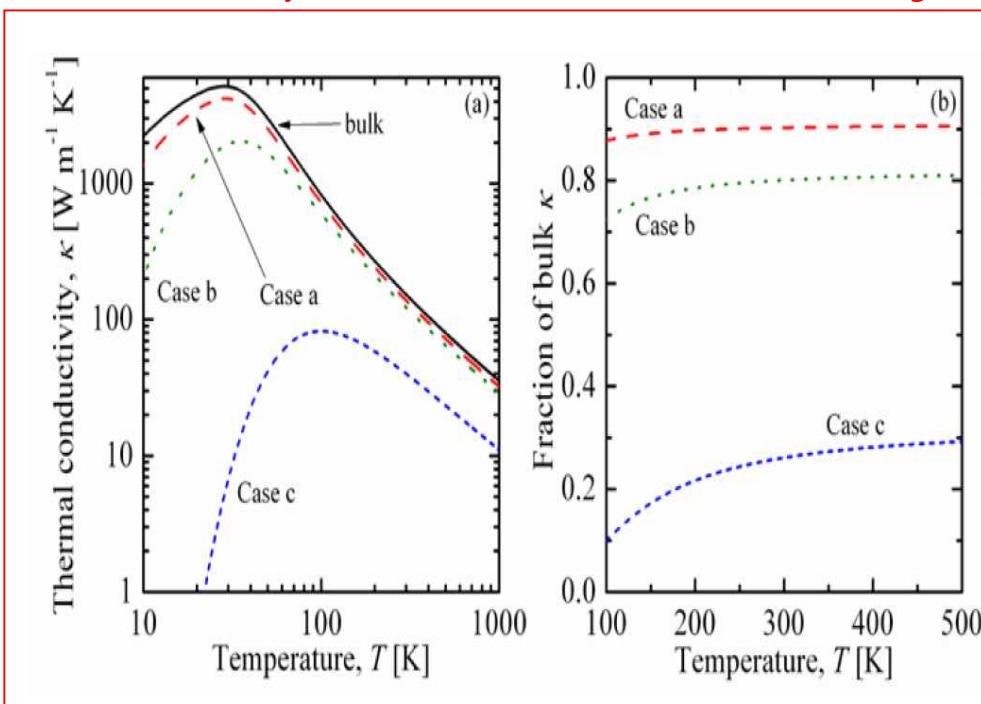
Manipulating the κ of Silicon



➤ **Cascaded PnC gaps 10GHz-to-1THz:**
Normalized Trans (dB) (Chirped Lattice)



➤ **Modified spectral thermal conductivity**



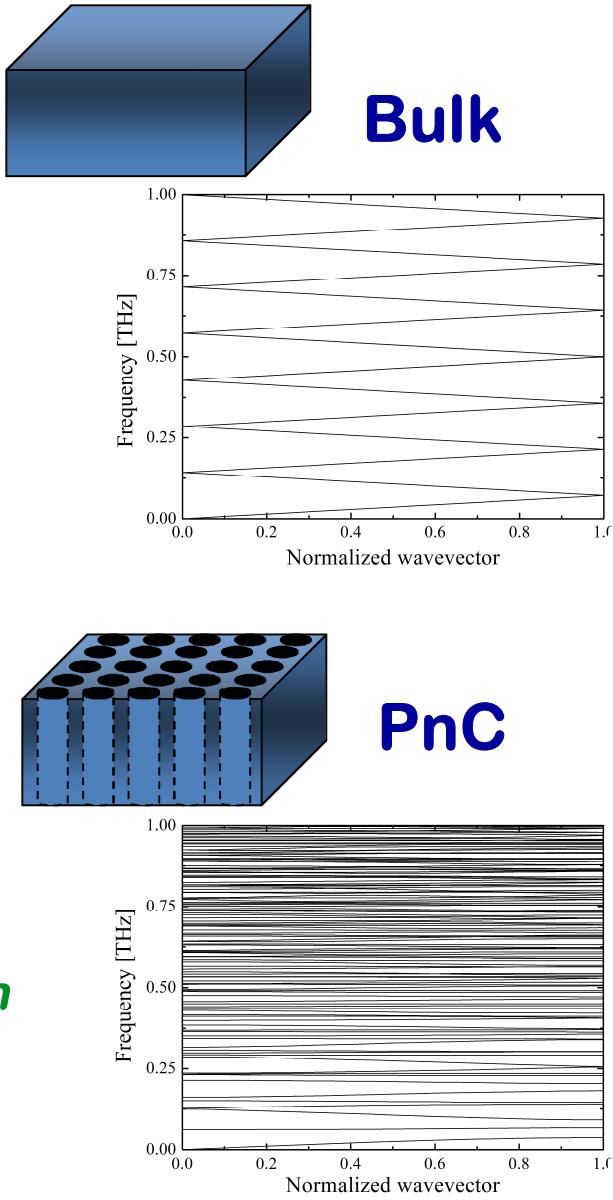
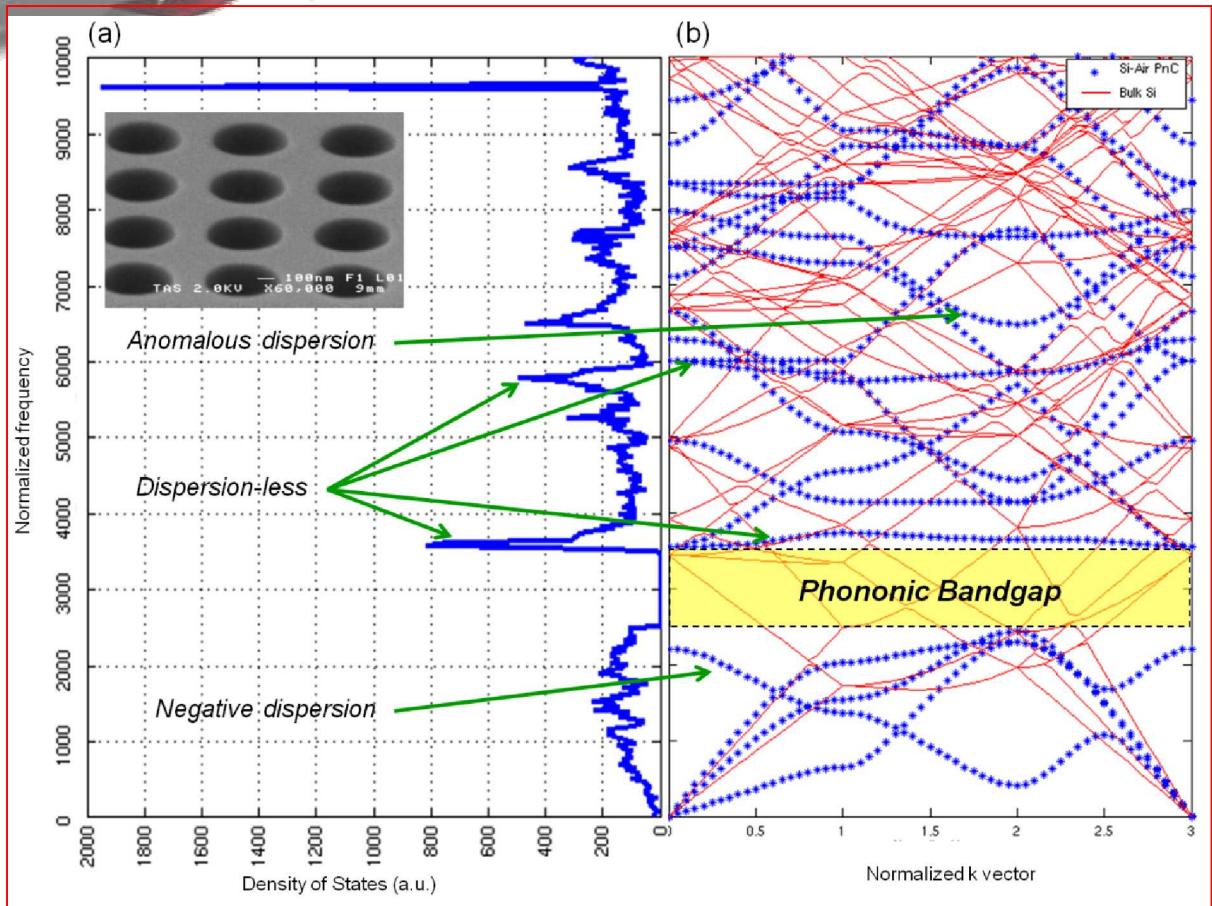
Thermal conductivity of Si assuming unmodified bulk dispersion with:

- **Case a:** *Suppression of 10GHz-to-0.5THz Phonons*
- **Case b:** *Suppression of 10GHz-to-1THz Phonons*
- **Case c:** *Suppression of 10GHz-to-4THz Phonons*

1- Hopkins, Rakich, Olsson III, El-Kady, and Phinney, "Origin of the reduction in phonon thermal conductivity of microporous solids," *Applied Physics Letters* 95, 161902 (2009).

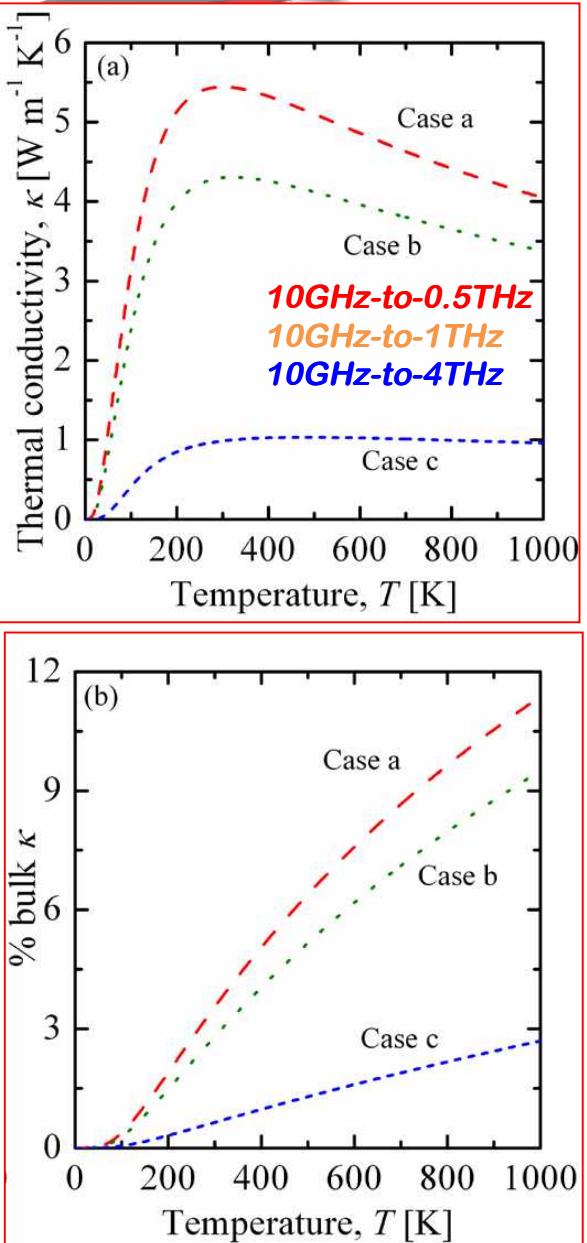
2- Hopkins, Phinney, Rakich, Olsson III, El-Kady, "Phonon considerations in the reduction of thermal conductivity in phononic crystals," currently under review JAPA.

Harmonic and Anharmonic Effects



- **Harmonic (coherent) Reflections → Bandgap creation**
- **Anharmonic Effects → Anomalous dispersion**
- **Flat Bands → Reduced group velocity**
- **Negative Bands → Backward propagation (backscattering)**

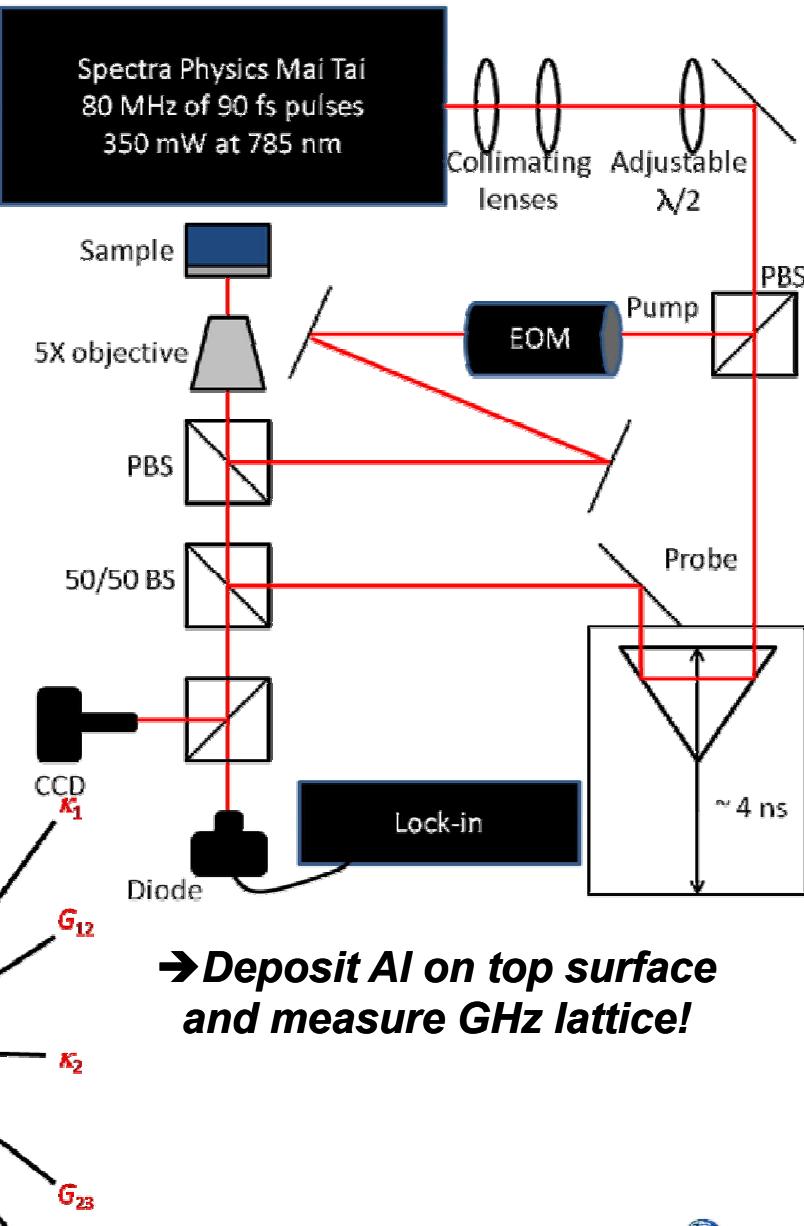
Si κ with Modified PnC Dispersion



Thermoreflectance signal directly proportional to temperature change

$$C \frac{\partial T}{\partial x} = -\kappa \frac{\partial^2 T}{\partial x^2}$$

Given temperature change with time, we fit the heat equation to the data to determine k



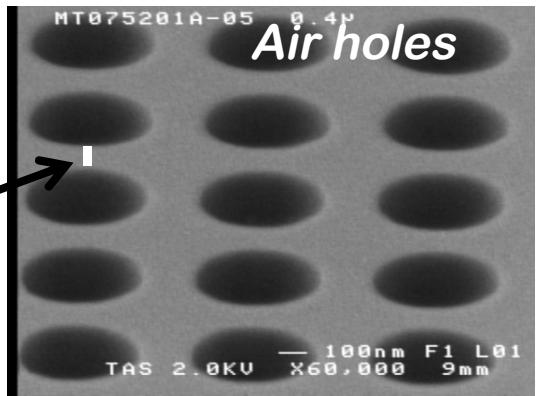
Measured κ of Silicon PnC

$$\kappa_{\omega,j} = \frac{1}{6\pi} \frac{\hbar^2 \omega_j^2(q)}{k_B T^2} \frac{\exp\left[\frac{\hbar\omega(q)}{k_B T}\right]}{\left(\exp\left[\frac{\hbar\omega(q)}{k_B T}\right] - 1\right)^2} v_j(q) \tau_j(q) q^2$$

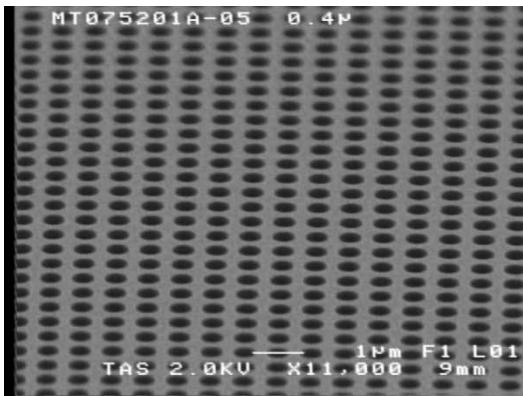
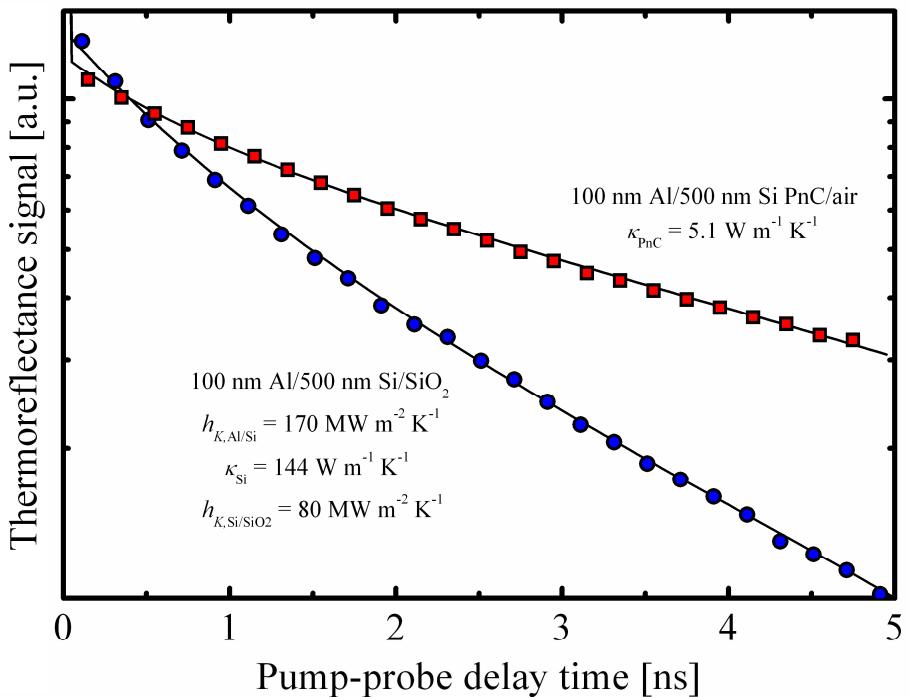
$$\frac{1}{\tau_j(q)} = \frac{1}{\tau_{Umklapp,j}} + \frac{1}{\tau_{impurity,j}} + \frac{1}{\tau_{boundary,j}}$$

$$\frac{1}{\tau_{Boundary,j}} = \frac{\partial \omega_j(q)}{\partial q} \frac{1}{L}$$

Limiting dimension,
 L
(min. feature size)



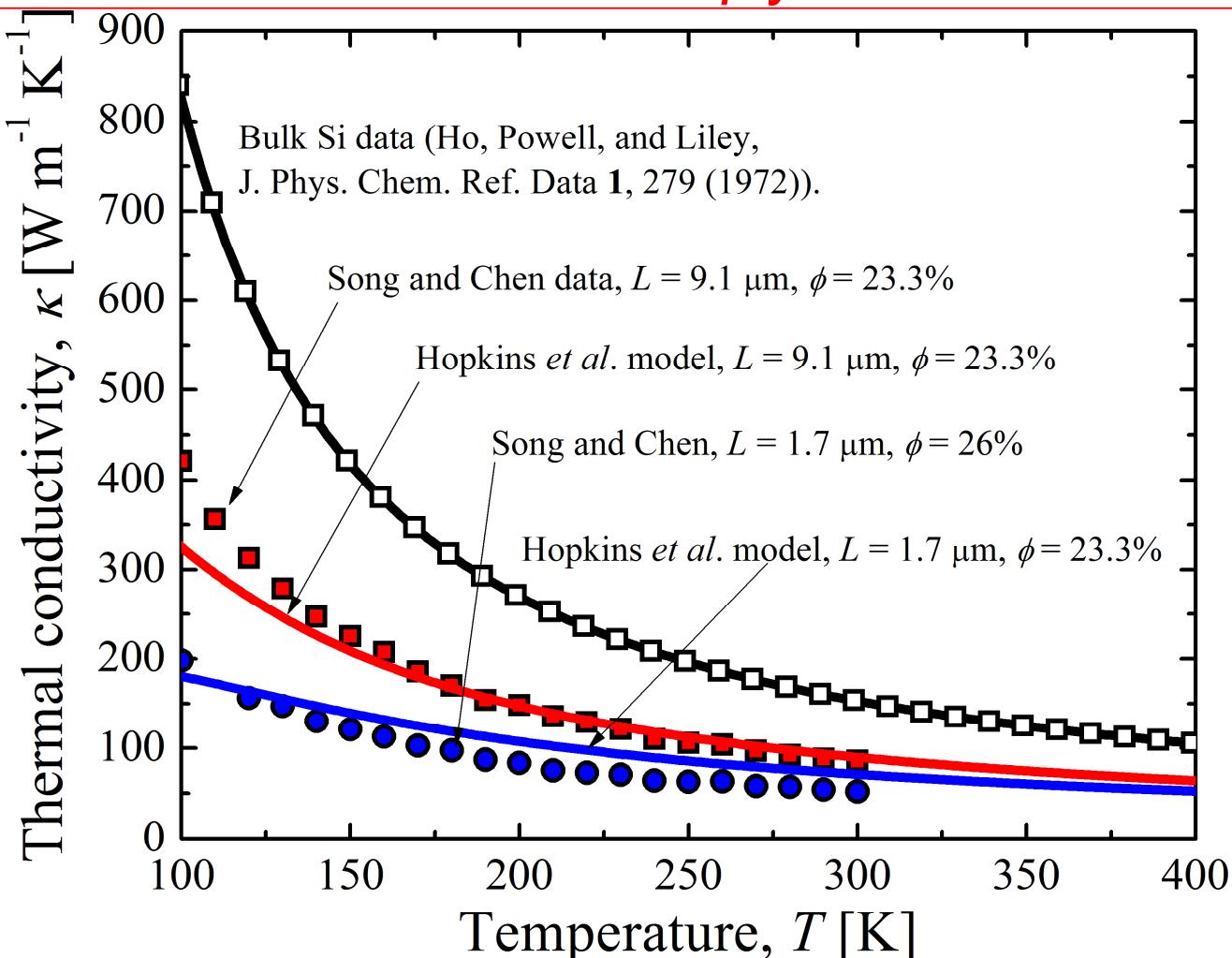
Thermal conductivity measurements on a 500nm-thick suspended PnC structure



$$\frac{\kappa_{PnC}}{\kappa_{bulk}} = 0.035$$

Understanding the Effect of Porosity:

Did we simply remove too much material?

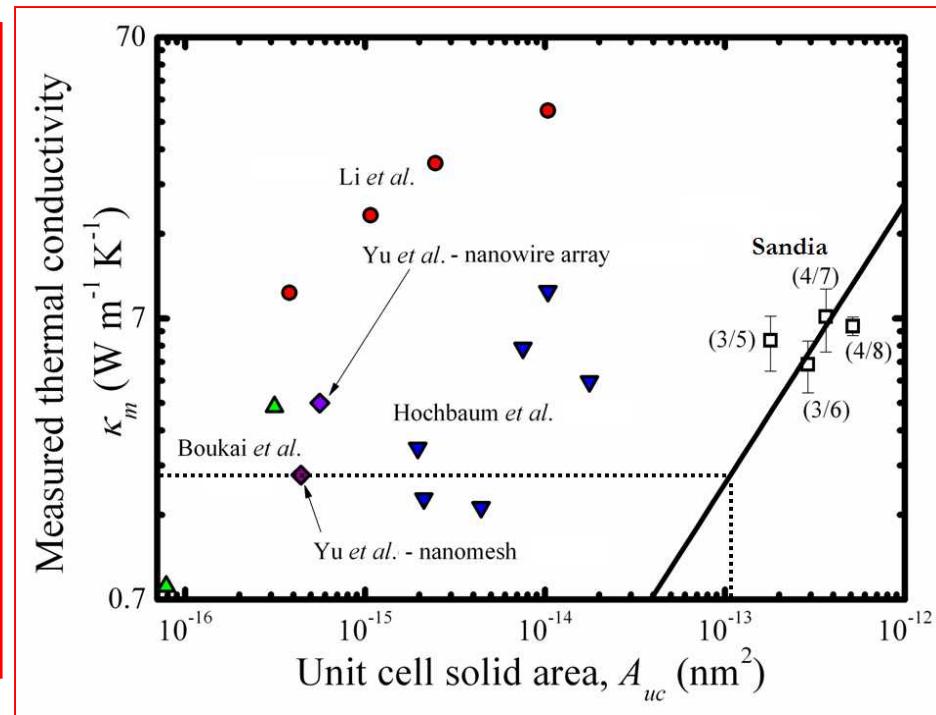
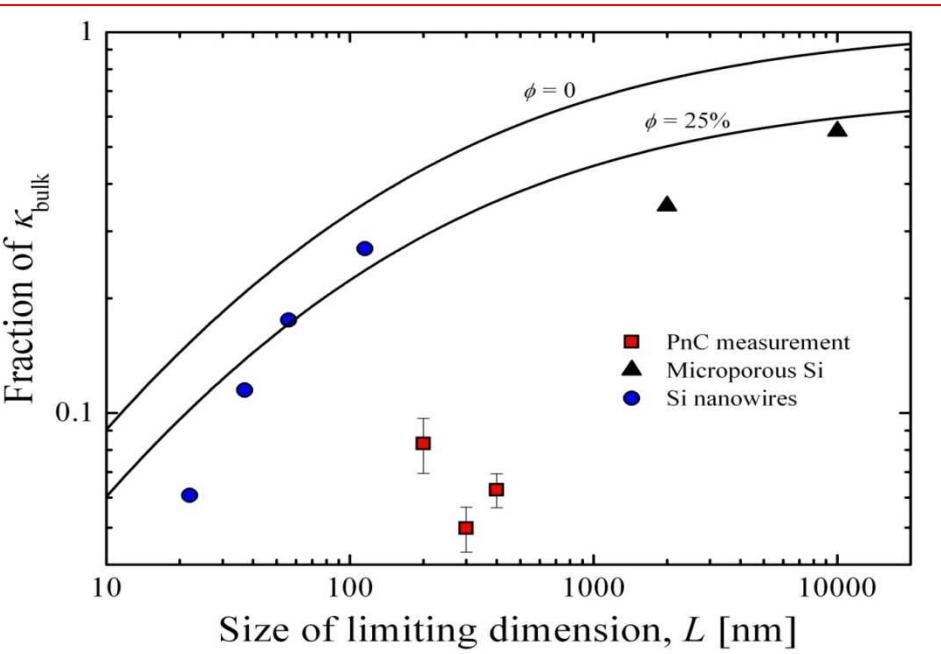


Porosity accounted for by “Eucken” model

$$\frac{\kappa_{\text{porous}}}{\kappa_{\text{solid}}} = \frac{1 - \phi}{1 + \frac{\phi}{2}}$$

Eucken, Forschung auf dem Gebiete des Ingenieurwesens Ausgabe B(Band 3): 3/4 VDI Forschungsheft 353 (1932).

An Order of Magnitude Lower κ (as compared to that predicted by the porosity argument)



Nanowires: $\varphi = 0$

Microporous Si: $\varphi \sim 25\%$

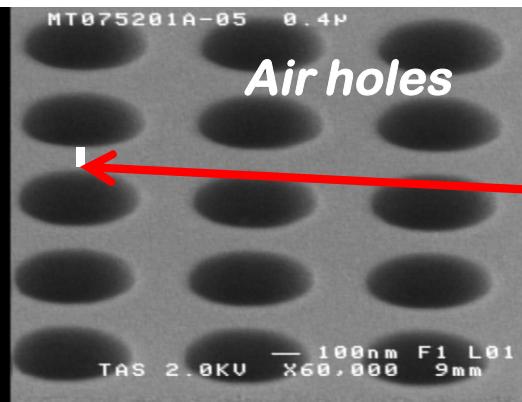
PnC: $\varphi < 20\%$

$$\frac{1}{\left(\frac{\kappa_{PnC}}{\kappa_{\text{bulk}}} \right)} = 500 !$$

**PnC outperforms nanowires
@ 2 orders of magnitude
larger limiting dimension (L)!**

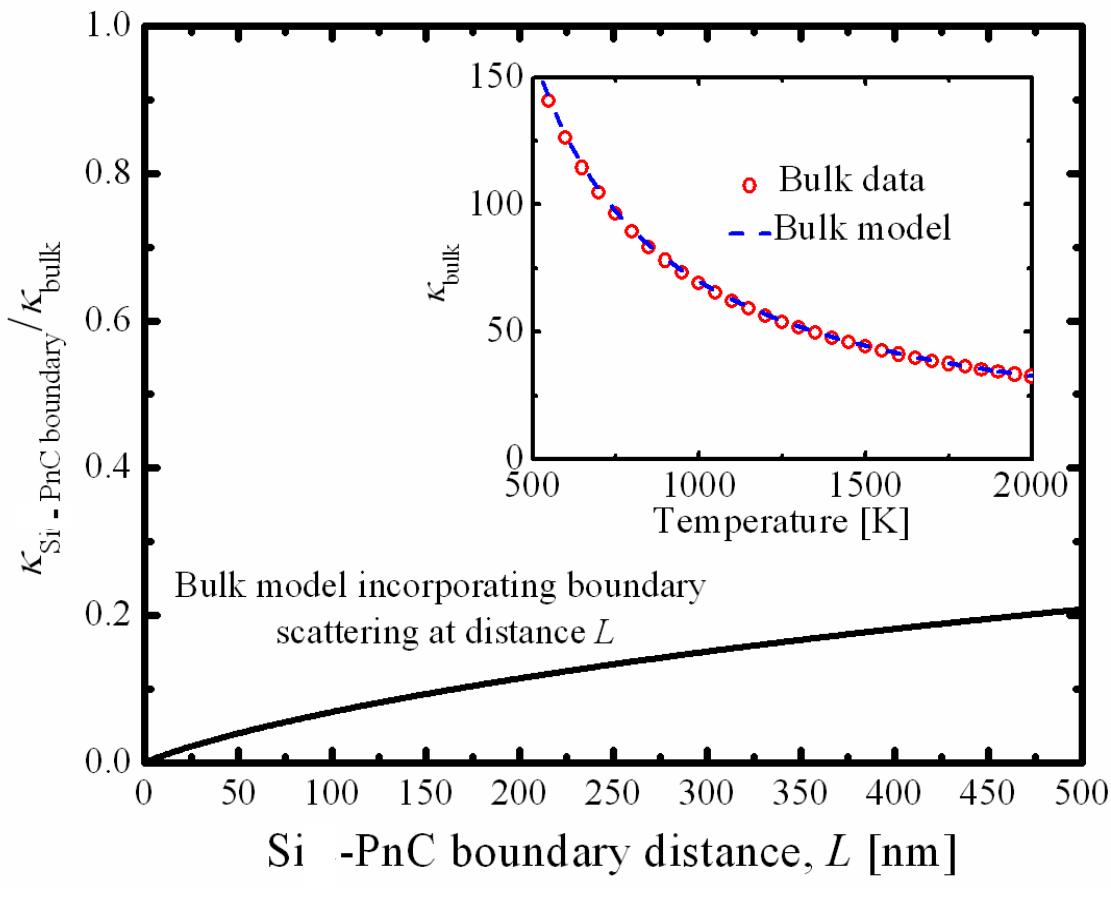
Since the mean free path of electrons is an order of magnitude lower than that of phonons, → Based solely on phonon thermal conductivity reduction, predicted room Temp. ZT enhancement in Si by a factor of 500!

How Can Micron-Size Holes Affect nm Wavelets Such as Phonons?



L,
limiting
dimension
(min. feature
size)

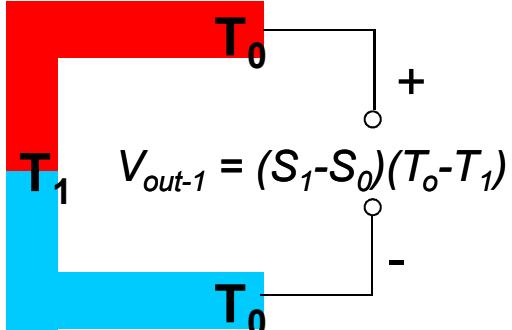
Ratio of the thermal conductivity of Si-PnC to that of bulk as a function of the minimum feature size, L , of the Si-PnC. Inset shows the accuracy with which the model predicts bulk behavior. Red is actual experimental data, and the dashed blue line is the result of model.



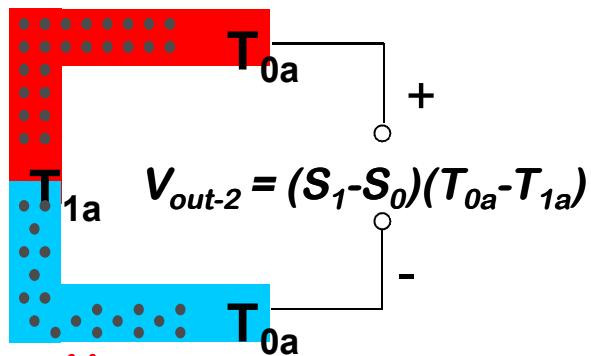
High-ZT PnC TE Device

- Thermal Energy Scavenging/TE Cooling

Generic Thermocouple: **PhonC Thermocouple:**



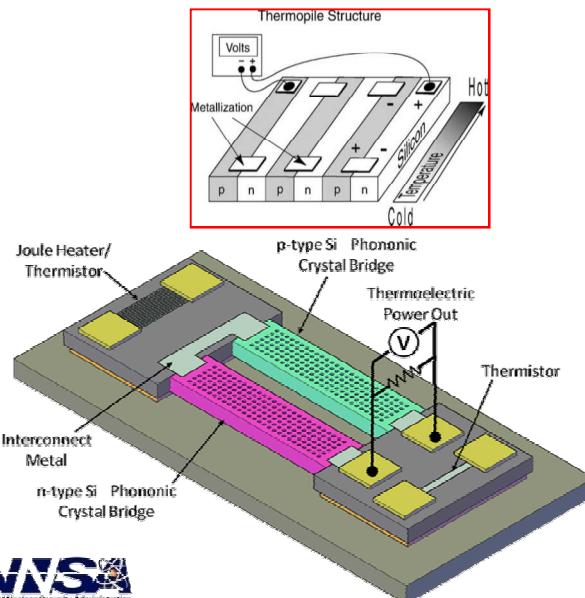
$$T_{0a} - T_{1a} > T_0 - T_1 \Rightarrow V_{out-2} > V_{out-1}$$



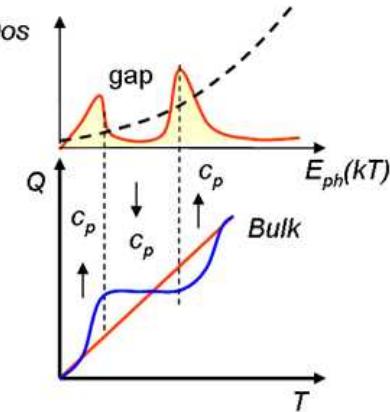
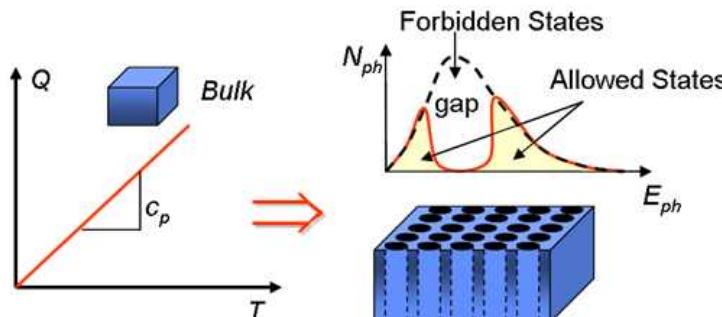
Seebeck coefficients of metals relative to platinum

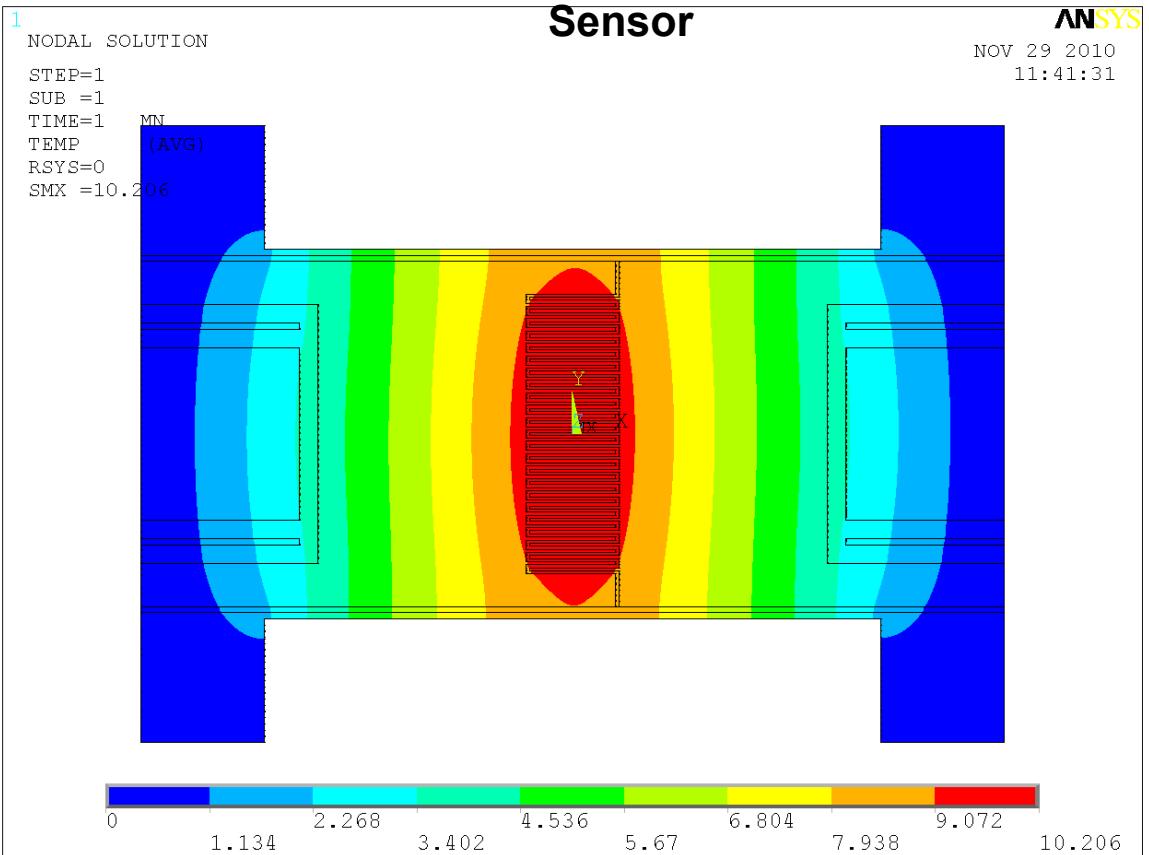
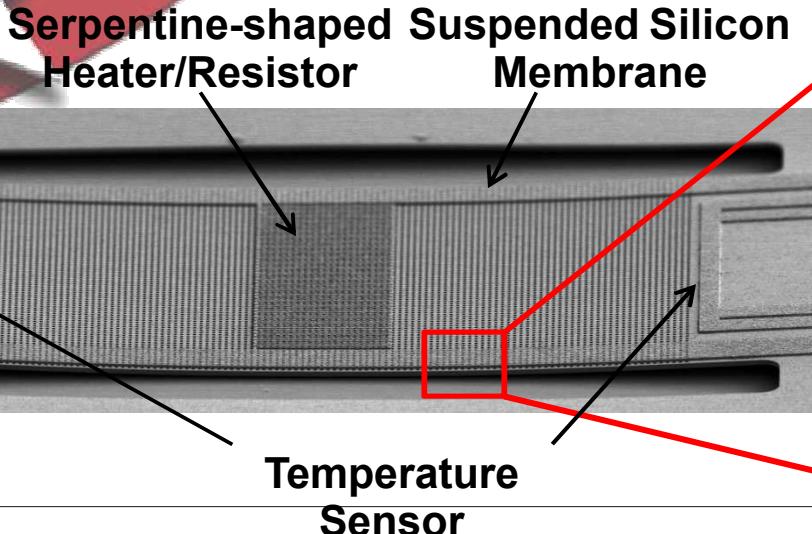
Material	Seebeck coefficient ($\mu\text{V}^\circ\text{C}$)
Antimony	+48.9
Chromel	+29.8
Tungsten	+11.2
Gold	+7.4
Copper	+7.6
Silver	+7.4
Aluminum	+4.2
p-Silicon, $\rho = 0.0035 \Omega\text{cm}$	+450
p-Germanium, $\rho = 0.0083 \Omega\text{cm}$	+420
Platinum	0.00
Calcium	-5.1
Alumel	-10.85
Cobalt	-13.3
Nickel	-14.5
Constantan	-37.25
Bismuth	-73.4
n-Silicon, $\rho = 0.0035 \Omega\text{cm}$	450
n-Germanium, $\rho = 0.69 \Omega\text{cm}$	-548

Phononic bandgap allows for simultaneous low thermopile series resistance (low losses) and high thermal isolation (high ΔT and ΔV)

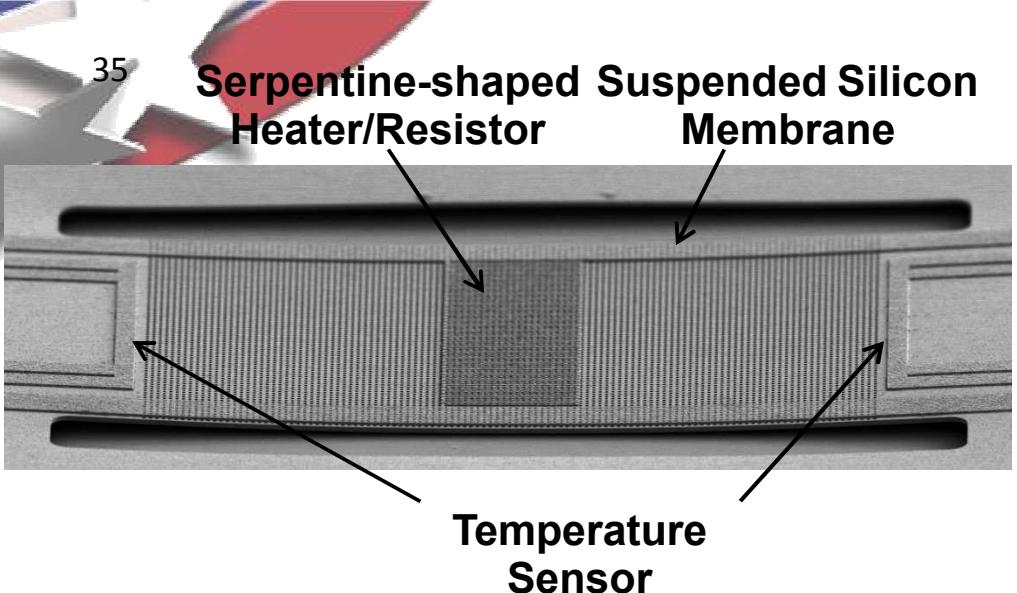


- Modification of the Global Heat Capacity:

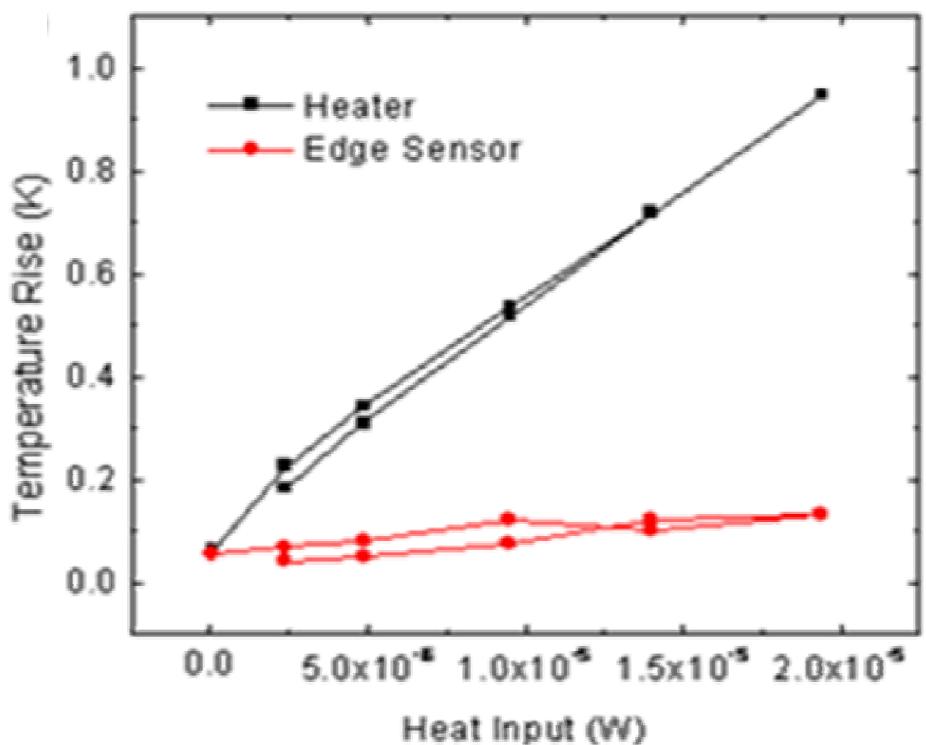




In-Plane PnC Structure Thermal Conductivity Measurement Testbench



Measurement of PnC Thermal Conductivity

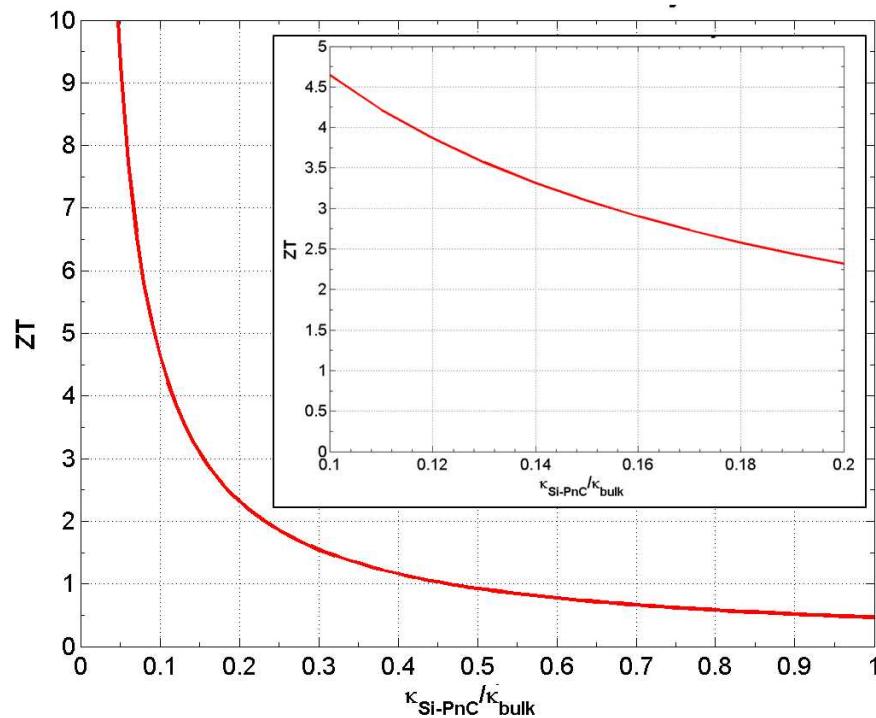
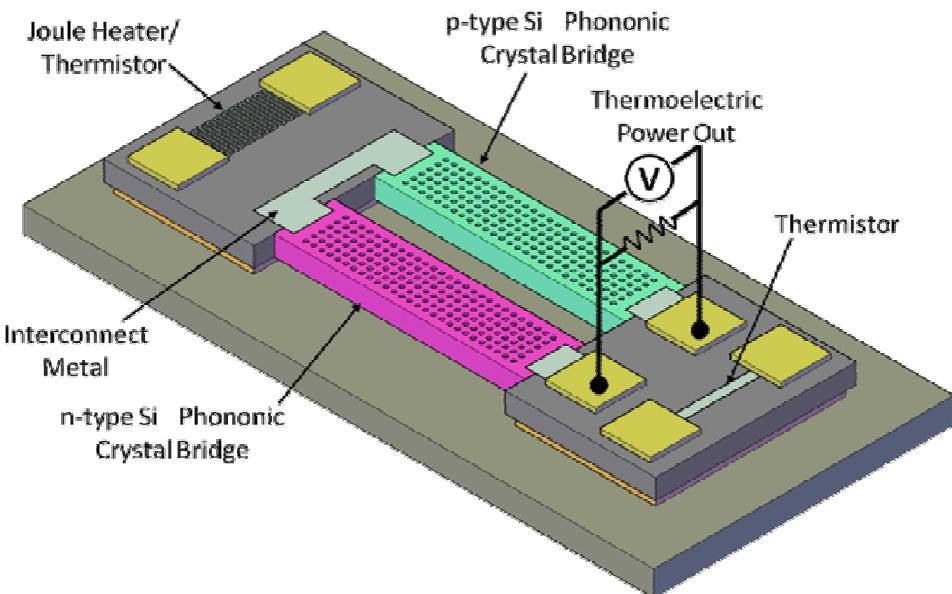


- Heater indicates heat pumped into the membrane
- Edge Sensor measures heat that has propagated through the sample
- In-plane thermal conductivity of the PnC calculated from its thermal resistance

High-ZT PnC Devices in Silicon

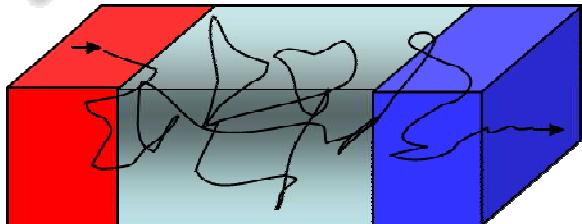
Performance Summary:

- **$ZT > 2$ predicted for a 80% reduction in bulk thermal conductivity**
- **$ZT > 4$ predicted for a 90% reduction in bulk thermal conductivity!**

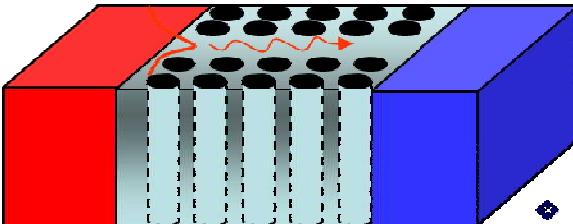


Future Applications

❖ Rapid Cooling?



Hot Side  Cold Side



Hot Side  Cold Side

❖ Concerns:

- Can we engineer the bands so that:

1. $V_g > V_d$?
2. Match guide impedance

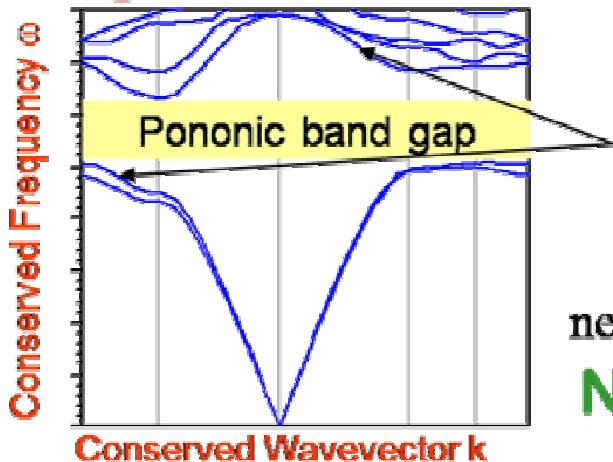
❖ Conventional:

- Random Phonon Scattering
- Overall Drift velocity v_d

❖ EBG Solution:

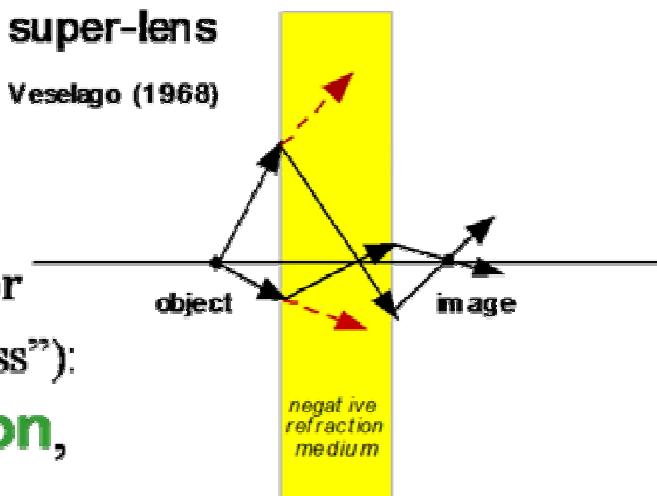
- Directive Phonon Guides
- Guide Group velocity v_g

❖ Negative Refraction and Acoustic Focusing:



Negative Sloping Bands  Negative Refraction
negative group-velocity or
negative curvature ("eff. mass"):

Negative refraction,
Super-Lensing



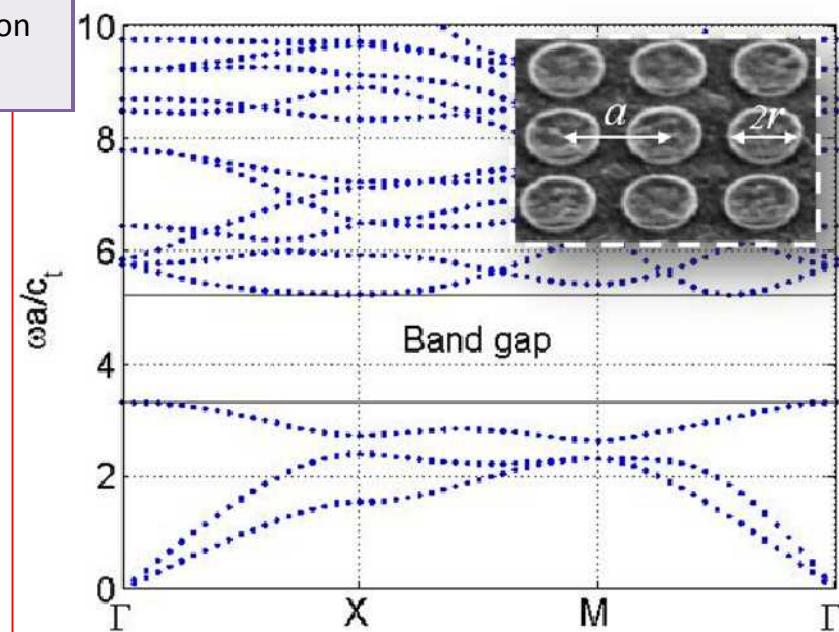
Conclusions

- ***Manipulation of phonons using phononic crystals***
 - ***UHF (38 GHz) operation***
 - ***Air-solid vs. solid-solid PnCs***
 - ***Roadmap to smaller features/higher frequencies***
- ***Reducing thermal conductivity via phonon manipulation***
 - ***Theoretically possible to push the ZT of Si to >2***
 - ***Enables ultra-efficient TE coolers/generators***

What's Next?

Temperature Dialing of Coherent vs. Incoherent PnC Effects

PnC Parameters				Fab Approach
ν	r	a	T	
10GHz	0.25μm	0.5μm	0.5K	Standard Lithography
100GHz	25nm	50nm	5K	Focused Ion Beam
~1 THz	5nm	10nm	25K	Focused Ion Beam



Broader Impact to Heat Capacity...

- *Modification of the Global Heat Capacity:*

